INTEGRATED CIRCUITS, SILICON MONOLITHIC,

CMOS ANALOGUE MULTIPLEXER/DEMULTIPLEXER,

BASED ON TYPE 4052B

ESCC Detail Specification No. 9202/048

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Pages 1 to 53

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space components
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1. GENERAL

1.1 SCOPE

This specification details the ratings, physical and electrical characteristics, test and inspection data for a silicon monolithic, CMOS Analogue Multiplexer/Demultiplexer, having fully buffered outputs, based on Type 4052B. It shall be read in conjunction with ESA/SCC Generic Specification No. 9000, the requirements of which are supplemented herein.

1.2 COMPONENT TYPE VARIANTS

Variants of the basic type integrated circuits specified herein, which are also covered by this specification, are given in Table 1(a).

1.3 MAXIMUM RATINGS

The maximum ratings, which shall not be exceeded at any time during use or storage, applicable to the integrated circuits specified herein, are as scheduled in Table 1(b).

Maximum ratings shall only be exceeded during testing to the extent specified in this specification and when stipulated in Test Methods and Procedures of the applicable ESA/SCC Generic Specification.

1.4 PARAMETER DERATING INFORMATION (FIGURE 1)

Not applicable.

1.5 PHYSICAL DIMENSIONS

As per Figure 2.

1.6 PIN ASSIGNMENT

As per Figure 3(a).

1.7 TRUTH TABLE

As per Figure 3(b).

1.8 CIRCUIT SCHEMATIC

As per Figure 3(c).

1.9 FUNCTIONAL DIAGRAM

As per Figure 3(d).

1.10 HANDLING PRECAUTIONS

These devices are susceptible to damage by electrostatic discharge. Therefore, suitable precautions shall be employed for protection during all phases of manufacture, testing, packaging, shipment and any handling. These components are Catagorised as Class 1 with a Minimum Critical Path Failure Voltage of 400Volts.

1.11 INPUT PROTECTION NETWORK

Double diode protection shall be incorporated into each input as shown in Figure 3(e).

TABLE 1(a) - TYPE VARIANTS

VARIANT	CASE	FIGURE	LEAD MATERIAL AND/OR FINISH
01	FLAT	2(a)	G2 or G8
02	FLAT	2(a)	G4
03	D.I.L.	2(b)	G2 or G8
04	D.I.L.	2(b)	G4
07	CHIP CARRIER	2(c)	2
08	D.I.L.	2(d)	G2
09	D.I.L.	2(d)	G4
10	SO CERAMIC	2(e)	G2
11	SO CERAMIC	2(e)	G4

TABLE 1(b) - MAXIMUM RATINGS

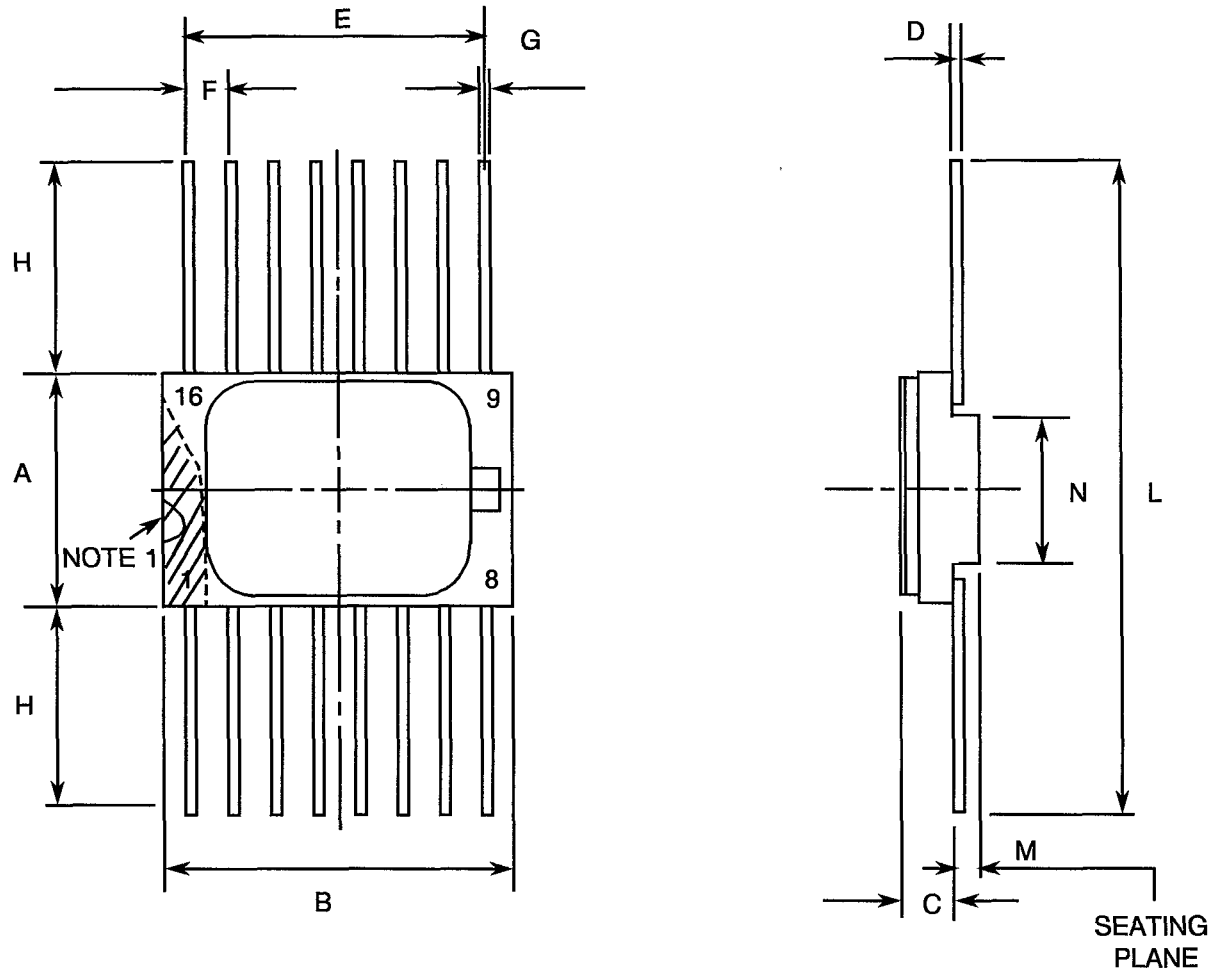
NO.	CHARACTERISTICS	SYMBOL	MAXIMUM RATINGS	UNITS	REMARKS
1	Supply Voltage	V_{DD}	-0.5 to +18	V	Note 1
2	Input Voltage	V_{IN}	-0.5 to V_{DD} + 0.5	V	Note 2 Power on
3	D.C. Input Current	$\pm I_{IN}$	10	mA	-
4	D.C. Output Current	$\pm I_O$	10	mA	Note 3
5	Device Dissipation	P_D	200	mWdc	Per Package
6	Output Dissipation	P_{DSO}	100	mWdc	Note 4
7	Operating Temperature Range	T_{op}	-55 to +125	°C	-
8	Storage Temperature Range	T_{stg}	-65 to +150	°C	-
9	Soldering Temperature For FP and DIP For CCP	T_{sol}	 +300 +245	°C	 Note 5 Note 6

NOTES

1. Device is functional from +3V to +15V with reference to V_{SS}.
2. V_{DD} +0.5V should not exceed +18V.
3. The maximum output current of any single output.
4. The maximum power dissipation of any single output.
5. Duration 10 seconds maximum at a distance of not less than 1.5mm from the device body and the same lead shall not be resoldered until 3 minutes have elapsed.
6. Duration 30 seconds maximum and the same terminal shall not be resoldered until 3 minutes have elapsed.

FIGURE 2 - PHYSICAL DIMENSIONS

FIGURE 2(a) - FLAT PACKAGE, 16-PIN

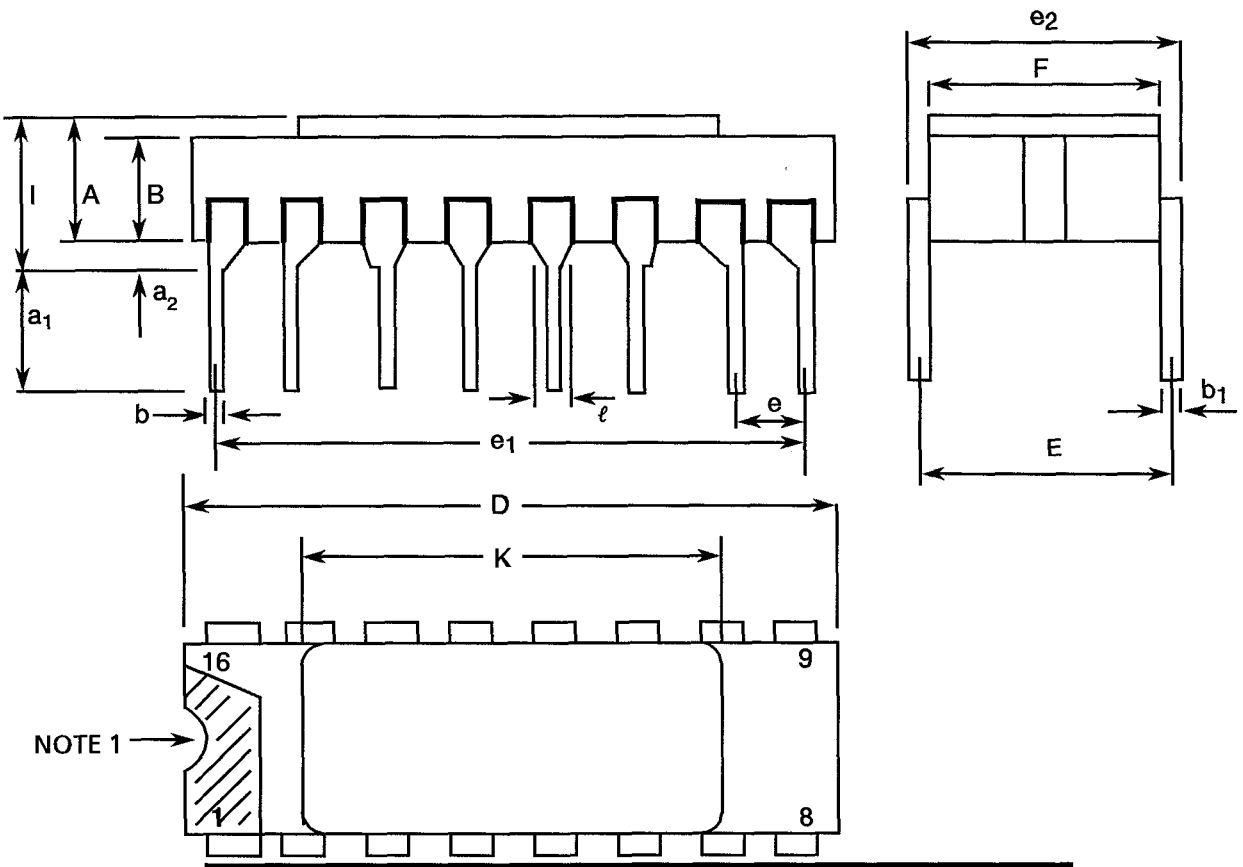


SYMBOL	MILLIMETRES		NOTES
	MIN	MAX	
A	6.75	7.06	
B	9.76	10.14	
C	1.49	1.95	
D	0.102	0.152	3
E	8.76	9.01	
F	1.27	TYPICAL	4
G	0.38	0.48	3
H	6.0	-	3
L	18.75	22.0	
M	0.33	0.43	
N	4.31	TYPICAL	

NOTES: See Page 12.

FIGURE 2 - PHYSICAL DIMENSIONS (CONTINUED)

FIGURE 2(b) - DUAL-IN-LINE PACKAGE, 16-PIN

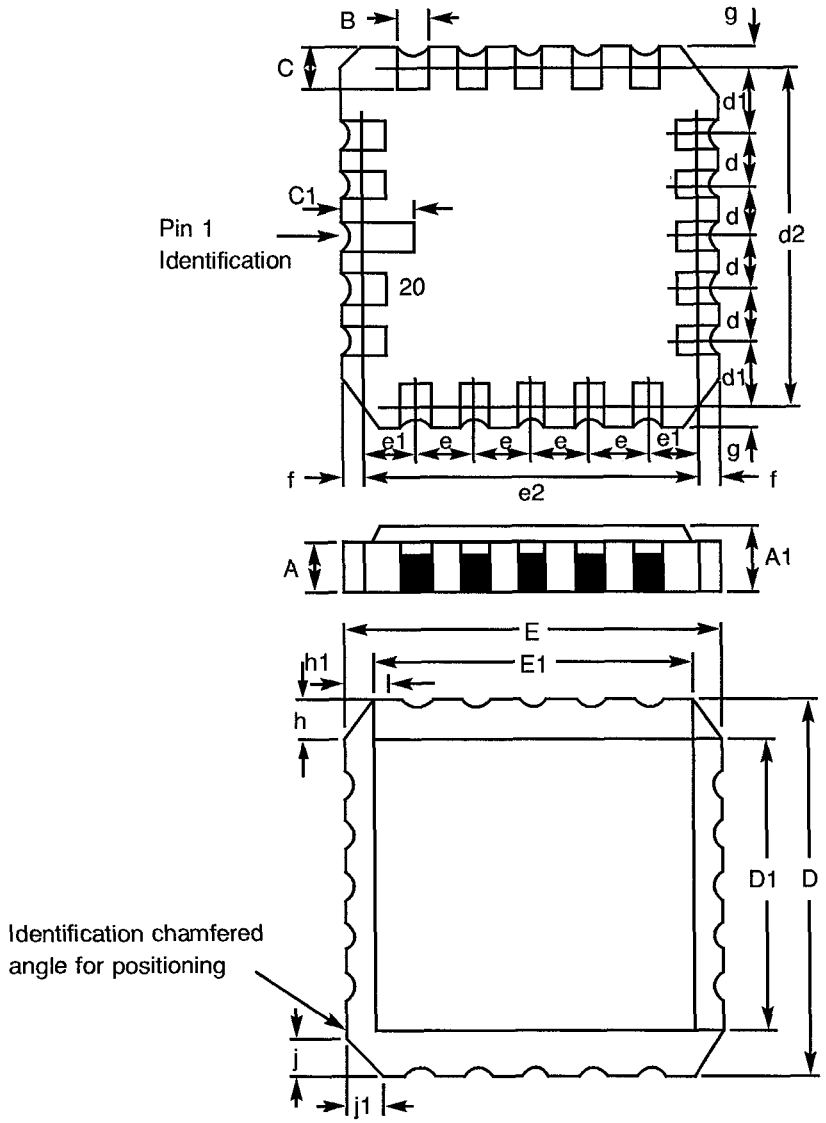


SYMBOL	MILLIMETRES		NOTES
	MIN	MAX	
A	2.10	2.54	
a_1	3.0	3.7	
a_2	0.63	1.14	2
B	1.82	2.23	
b	0.40	0.50	3
b_1	0.20	0.30	3
D	18.79	19.20	
E	7.36	7.87	
e	2.41	2.67	4
e_1	17.65	17.90	
e_2	7.62	8.12	
F	7.11	7.62	
I	-	3.70	
K	10.90	12.10	
ℓ	1.27	TYPICAL	

NOTES: See Page 12.

FIGURE 2 - PHYSICAL DIMENSIONS (CONTINUED)

FIGURE 2(c) - CHIP CARRIER - 20-TERMINAL

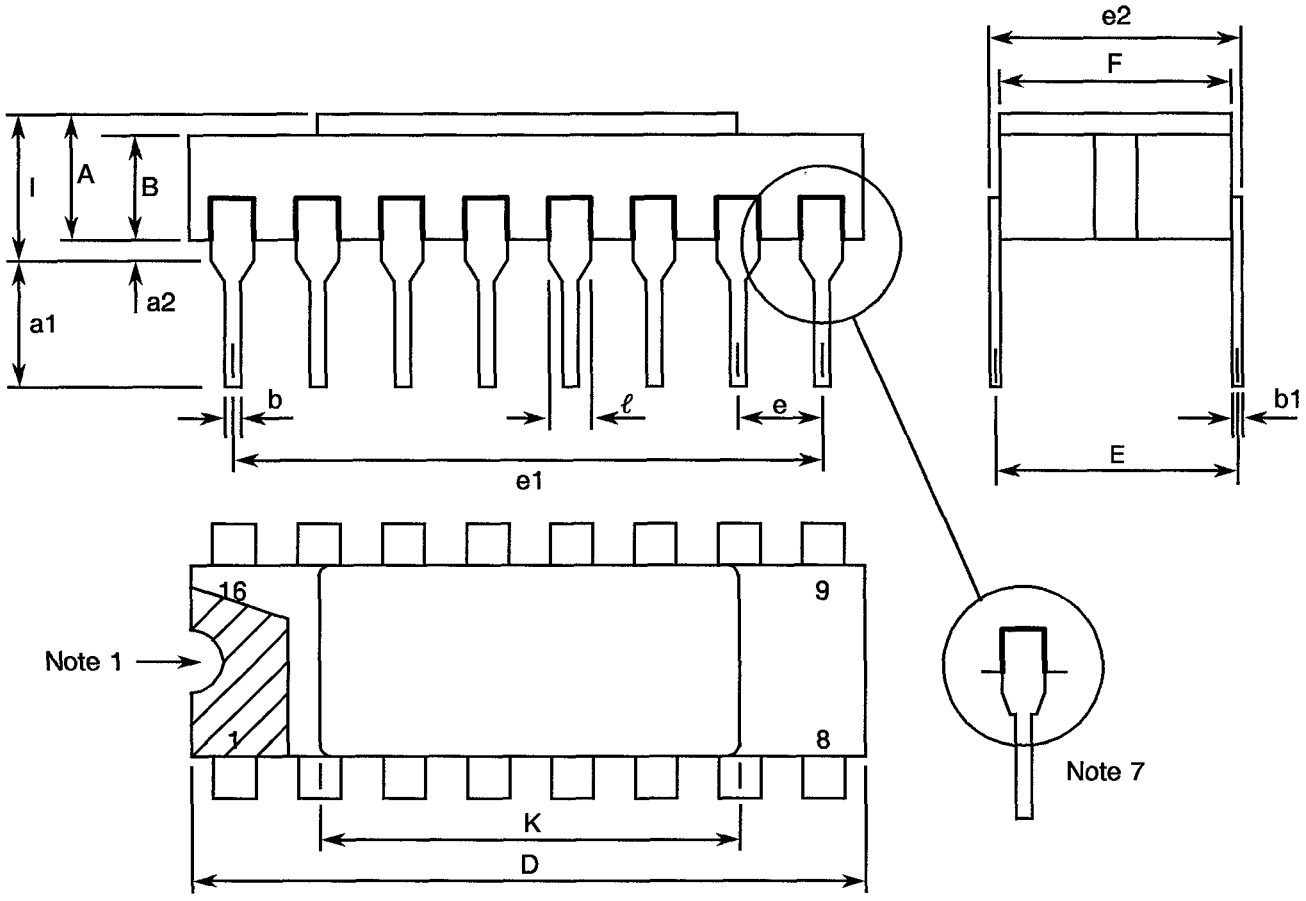


DIMENSIONS	MILLIMETRES		NOTES
	MIN	MAX	
A	1.14	1.95	
A1	1.63	2.36	
B	0.55	0.72	3
C	1.06	1.47	3
C_1	1.91	2.41	
D	8.67	9.09	
D1	7.21	7.52	
d, d1	1.27	TYPICAL	4
d2	7.62	TYPICAL	
E	8.67	9.09	
E1	7.21	7.52	
e, e1	1.27	TYPICAL	4
e2	7.62	TYPICAL	
f, g	-	0.76	
h, h1	1.01	TYPICAL	6
j, j1	0.51	TYPICAL	5

NOTES: See Page 12.

FIGURE 2 - PHYSICAL DIMENSIONS (CONTINUED)

FIGURE 2(d) - DUAL-IN-LINE PACKAGE, 16-PIN

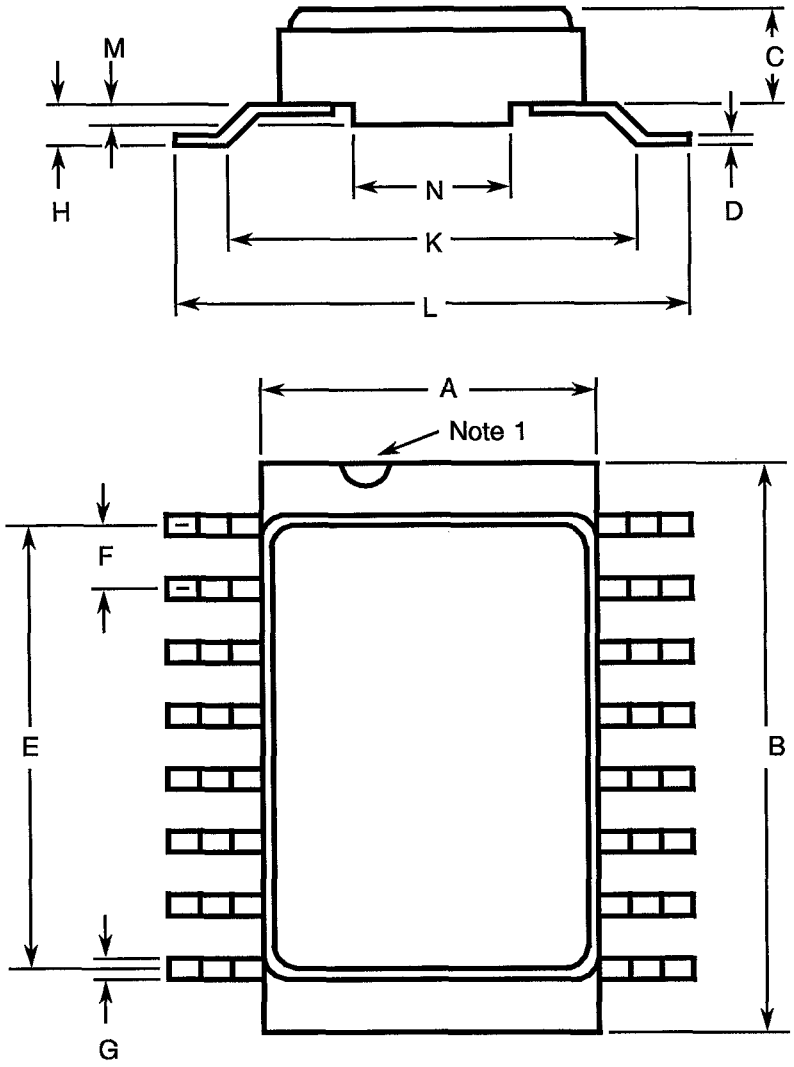


SYMBOL	MILLIMETRES		NOTES
	MIN	MAX	
A	2.10	2.71	
a1	3.00	3.70	
a2	0.63	1.14	2
B	1.82	2.39	
b	0.40	0.50	3
b1	0.20	0.30	3
D	20.06	20.58	
E	7.36	7.87	
e	2.54 TYPICAL		4
e1	17.65	17.90	
e2	7.62	8.12	
F	7.29	7.70	
I	-	3.83	
K	10.90	12.10	
ℓ	1.14	1.50	

NOTES: See Page 12.

FIGURE 2 - PHYSICAL DIMENSIONS (CONTINUED)

FIGURE 2(e) - SMALL OUTLINE CERAMIC PACKAGE, 16-PIN



SYMBOL	MILLIMETRES		NOTES
	MIN.	MAX.	
A	6.75	7.06	
B	9.76	10.14	
C	1.49	1.95	
D	0.102	0.152	3
E	8.76	9.01	
F	1.27 TYPICAL		4
G	0.38	0.48	3
H	0.60	0.90	3
K	9.00 TYPICAL		
L	10	10.65	
M	0.33	0.43	
N	4.31 TYPICAL		

NOTES: See Page 12.

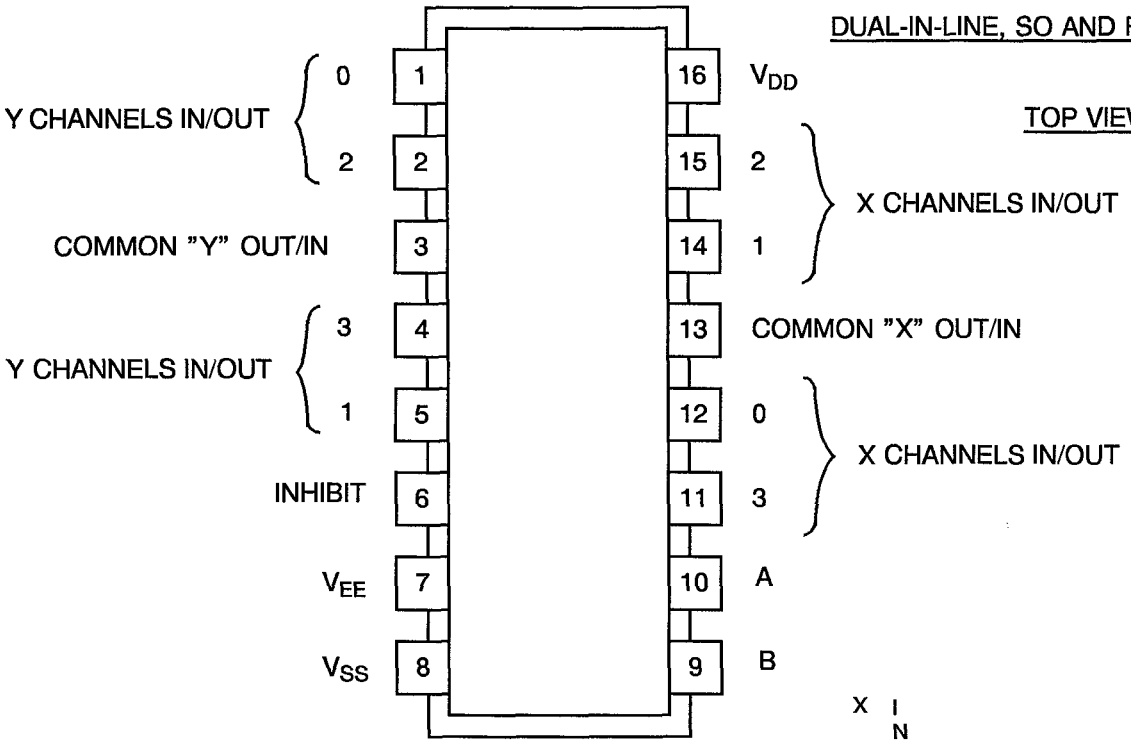
FIGURE 2 - PHYSICAL DIMENSIONS (CONTINUED)

NOTES TO FIGURES 2(a) TO 2(e) INCLUSIVE

1. Index area: a notch, letter or dot shall be located adjacent to Pin 1 and shall be within the shaded area shown. For chip carrier packages the index shall be as defined in Figure 2(c).
2. The dimension shall be measured from the seating plane to the base plane.
3. All leads or terminals.
4. 16-pin packages : 14 spaces.
   20-terminal packages : 12 spaces.
5. Index corner only.
6. Three non-index corners
7. For all pins, either pin shape may be supplied.

FIGURE 3(a) - PIN ASSIGNMENT

DUAL-IN-LINE, SO AND FLAT PACKAGES



CHIP CARRIER PACKAGE

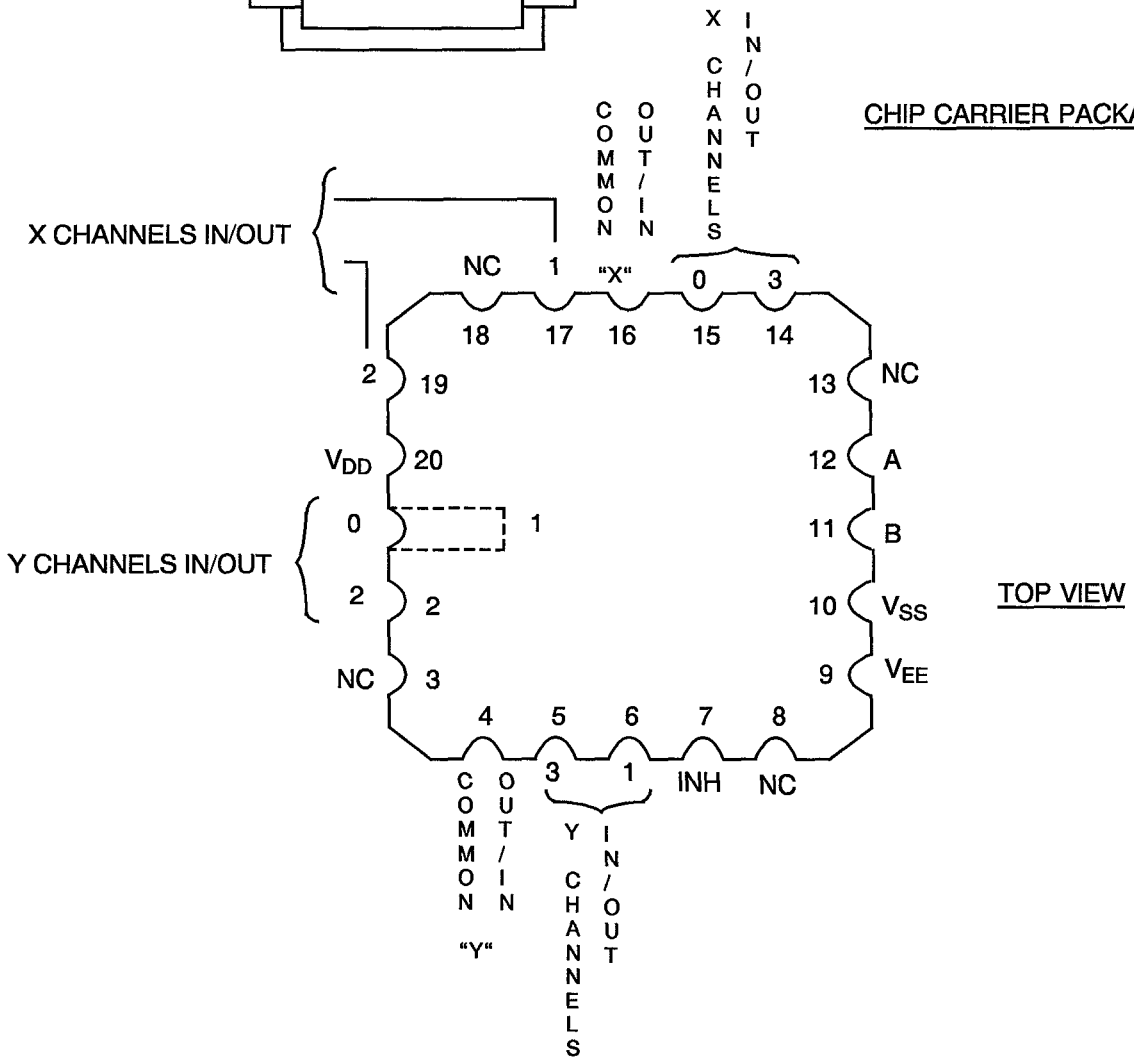


FIGURE 3(a) - PIN ASSIGNMENT (CONT'D)

FLAT PACKAGE, SO AND DUAL-IN-LINE TO CHIP CARRIER PIN ASSIGNMENT

FLAT PACKAGE, SO AND DUAL-IN-LINE PIN OUTS	1	2	3	4	5	6	7	8	9	10	11	12	13	14	15	16
CHIP CARRIER PIN OUTS	1	2	4	5	6	7	9	10	11	12	14	15	16	17	19	20

FIGURE 3(b) - TRUTH TABLE

INPUT STATES			"ON" CHANNEL(S)
INHIBIT	B	A	
L	L	L	0_X, 0_Y
L	L	H	1_X, 1_Y
L	H	L	2_X, 2_Y
L	H	H	3_X, 3_Y
H	X	X	None

NOTES 1. Logic Level Definitions: L = Low Level, H = High Level, X = Don't Care.

FIGURE 3(c) - CIRCUIT SCHEMATIC

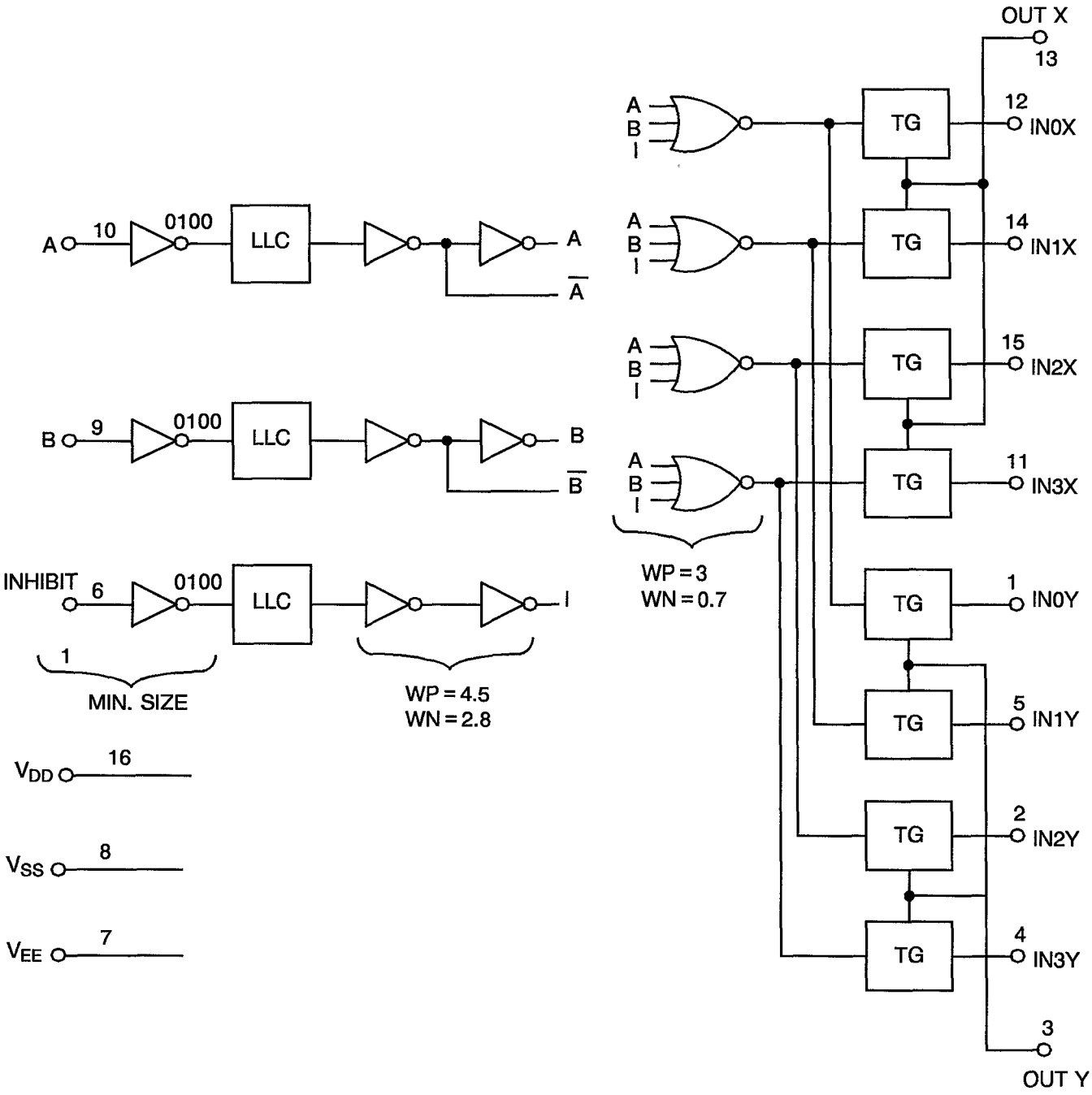


FIGURE 3(d) - FUNCTIONAL DIAGRAM

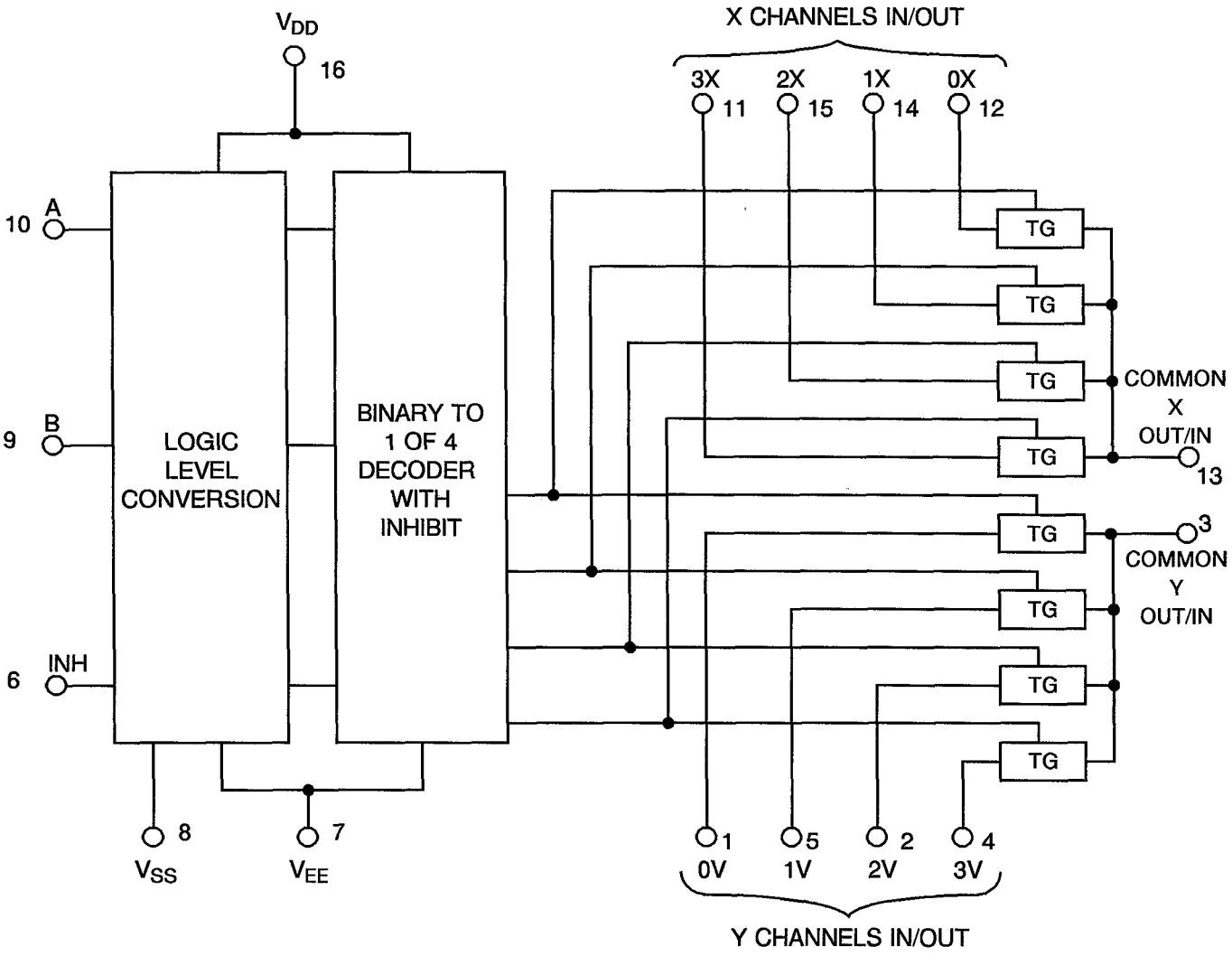
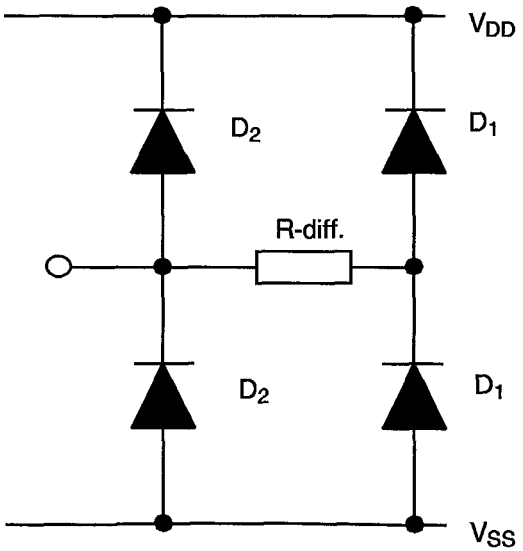


FIGURE 3(e) - INPUT PROTECTION NETWORK



2. APPLICABLE DOCUMENTS

The following documents form part of this specification and shall be read in conjunction with it:-

(a) ESA/SCC Generic Specification No. 9000 for Integrated Circuits.

(b) MIL-STD-883, Test Methods and Procedures for Micro-electronics.

3. TERMS, DEFINITIONS, ABBREVIATIONS, SYMBOLS AND UNITS

For the purpose of this specification, the terms, definitions, abbreviations, symbols and units specified in ESA/SCC Basic Specification No. 21300 shall apply. In addition, the following abbreviations are used:

V_{IC} = Input Clamp Voltage
P_{DSO} = Single Output Power Dissipation
CKT = Circuit
I_{OFF} = Channel Off Leakage Current
R_{ON} = Channel On Resistance
C_{INC} = Channel Input Capacitance
C_{OC} = Channel Output Capacitance

4. REQUIREMENTS

4.1 GENERAL

The complete requirements for procurement of the integrated circuits specified herein are stated in this specification and ESA/SCC Generic Specification No. 9000 for Integrated Circuits. Deviations from the Generic Specification, applicable to this specification only, are listed in Para. 4.2.

Deviations from the applicable Generic Specification and this Detail Specification, formally agreed with specific Manufacturers on the basis that the alternative requirements are equivalant to the ESA/SCC requirements and do not affect the components' reliability, are listed in the appendices attached to this specification.

4.2 DEVIATIONS FROM GENERIC SPECIFICATION

4.2.1 Deviations from Special In-process Controls

None.

4.2.2 Deviations from Final Production Tests (Chart II)

None.

4.2.3 Deviations from Burn-in Tests (Chart III)

4.2.3.1 Deviations from High Temperature Reverse Bias (H.T.R.B.)

Prior to operating power burn-in, a high temperature reverse bias (H.T.R.B.) screen at +125°C shall be added for the N-Channel and then for the P-Channel in accordance with Tables 5(a) and 5(b) of this specification. Each exposure to H.T.R.B. shall be 72 hours and Table 4 Parameter Drift Values shall be applied at 0 and 144 hours.

4.2.4 Deviations from Qualification Tests (Chart IV)

None.

4.2.5 Deviations from Lot Acceptance Tests (Chart V)

None.

4.3 MECHANICAL REQUIREMENTS

4.3.1 Dimension Check

The dimensions of the integrated circuits specified herein shall be checked. They shall conform to those shown in Figure 2.

4.3.2 Weight

The maximum weight of the integrated circuits specified herein shall be 1.5 grammes for the dual-in-line package, 0.6 grammes for the flat and SO packages and 0.52 grammes for the chip carrier.

4.4 MATERIALS AND FINISHES

The materials shall be as specified herein. Where a definite material is not specified, a material which will enable the integrated circuits specified herein to meet the performance requirements of this specification shall be used. Acceptance or approval of any constituent material does not guarantee acceptance of the finished product.

4.4.1 Case

The case shall be hermetically sealed and have a metal body with hard glass seals or a ceramic body and the lids shall be welded, brazed or preform-soldered.

4.4.2 Lead Material and Finish

For dual-in-line and flat packages, the material shall be Type 'G' with either Type '4' or Type '2 or 8' finish in accordance with ESA/SCC Basic Specification No. 23500. For chip carrier packages the finish shall be Type '2' in accordance with ESA/SCC Basic Specification No. 23500. For SO ceramic packages, the material shall be Type 'G' with either Type '2' or Type '4' finish in accordance with ESA/SCC Basic Specification No. 23500. (See Table 1(a) for Type Variants).

4.5 MARKING

4.5.1 General

The marking of all components delivered to this specification shall be in accordance with the requirements of ESA/SCC Basic Specification No. 21700. Each component shall be marked in respect of:-

(a) Lead Identification.

(b) The SCC Component Number.

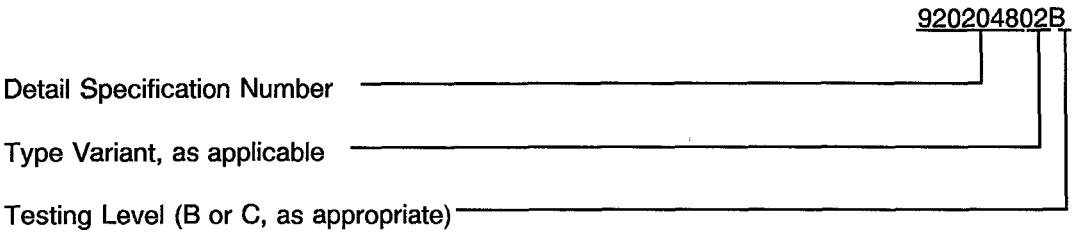
(c) Traceability Information.

4.5.2 Lead Identification

For dual-in-line, flat and SO packages, an index shall be located at the top of the package in the position defined in Note 1 to Figure 2 or, alternatively, a tab may be used to identify Pin No. 1. The pin numbering must be read with the index or tab on the left-hand side. For chip carrier packages, the index shall be as defined by Figure 2(c).

4.5.3 The SCC Component Number

Each component shall bear the SCC Component Number which shall be constituted and marked as follows:



4.5.4 Traceability Information

Each component shall be marked in respect of traceability information in accordance with the requirements of ESA/SCC Basic Specification No. 21700.

4.6 ELECTRICAL MEASUREMENTS

4.6.1 Electrical Measurements at Room Temperature

The parameters to be measured in respect of electrical characteristics are scheduled in Table 2. Unless otherwise specified, the measurements shall be performed at $T_{amb} = +22 \pm 3$ °C.

4.6.2 Electrical Measurements at High and Low Temperatures

The parameters to be measured at high and low temperatures are scheduled in Table 3. The measurements shall be performed at $T_{amb} = +125(+0\text{-}5)$ °C and $-55(+5\text{-}0)$ °C respectively.

4.6.3 Circuits for Electrical Measurements

Circuits and functional test sequence for use in performing electrical measurements listed in Tables 2 and 3 of this specification are shown in Figure 4.

4.7 BURN-IN TESTS

4.7.1 Parameter Drift Values

The parameter drift values applicable to burn-in are specified in Table 4 of this specification. Unless otherwise stated, measurements shall be performed at $+22 \pm 3$ °C. The parameter drift values (Δ) applicable to the parameters scheduled, shall not be exceeded. In addition to these drift value requirements, the appropriate limit value specified for a given parameter in Table 2 shall not be exceeded.

4.7.2 Conditions for H.T.R.B. and Burn-in

The requirements for H.T.R.B. and Burn-in are specified in Section 7 of ESA/SCC Generic Specification No. 9000. The conditions for H.T.R.B. and Burn-in shall be as specified in Tables 5(a), 5(b) and 5(c) of this specification.

4.7.3 Electrical Circuits for H.T.R.B and Burn-in

Circuits for use in performing the H.T.R.B. and Burn-in tests are shown in Figures 5(a), 5(b) and 5(c) of this specification.

TABLE 2 - ELECTRICAL MEASUREMENTS AT ROOM TEMPERATURE - d.c. PARAMETERS

NO.	CHARACTERISTICS	SYMBOL	TEST METHOD MIL-STD 883	TEST FIG.	TEST CONDITIONS (PINS UNDER TEST D/F = DIP AND FP C = CCP)	LIMITS		UNIT
						MIN	MAX	
1	Functional Test	-	-	4(a)	Verify Truth Table without Load. V_{DD} = 3Vdc, V_{SS} = V_{EE} = 0Vdc Notes 1 and 2	-	-	-
2	Functional Test	-	-	4(a)	Verify Truth Table without Load. V_{DD} = 15Vdc, V_{SS} = V_{EE} = 0Vdc Notes 1 and 2	-	-	-
3 to 7	Quiescent Current	I_{DD}	3005	4(b)	V_{IL} = 0Vdc, V_{IH} = 15Vdc V_{DD} = 15Vdc, V_{SS} = V_{EE} = 0Vdc Note 3 (Pin D/F 16) (Pin C 20)	-	1.0	µA
8 to 10	Input Current Low Level Address or Inhibit	I_{IL}	3009	4(c)	V_{IN} (Under Test) = 0Vdc V_{IN} (Other Inputs) = 15Vdc V_{DD} = 15Vdc, V_{SS} = V_{EE} = 0Vdc (Pins D/F 6-9-10) (Pins C 7-11-12)	-	-50	nA
11 to 13	Input Current High Level Address or Inhibit	I_{IH}	3010	4(d)	V_{IN} (Under Test) = 15Vdc V_{IN} (Other Inputs) = 0Vdc V_{DD} = 15Vdc, V_{SS} = V_{EE} = 0Vdc (Pins D/F 6-9-10) (Pins C 7-11-12)	-	50	nA
14 to 21	Channel Off Leakage Current (Any Channel)	I_{OFF1}	-	4(e)	V_{IN} (Inhibit) = 15Vdc V_{IN} (Address Inputs) = 0Vdc V_{IN} (Channel I/O) = 15Vdc V_{IN} (Common I/O) = 0Vdc V_{DD} = 15Vdc, V_{SS} = V_{EE} = 0Vdc Pins D/F — Pins C 1 to 3 — 1 to 4 2 to 3 — 2 to 4 4 to 3 — 5 to 4 5 to 3 — 6 to 4 11 to 13 — 14 to 16 12 to 13 — 15 to 16 14 to 13 — 17 to 16 15 to 13 — 19 to 16	-	-100	nA

NOTES: See Page 25.

TABLE 2 - ELECTRICAL MEASUREMENTS AT ROOM TEMPERATURE - d.c. PARAMETERS (CONT'D)

NO.	CHARACTERISTICS	SYMBOL	TEST METHOD MIL-STD 883	TEST FIG.	TEST CONDITIONS (PINS UNDER TEST D/F = DIP AND FP C = CCP)	LIMITS MIN	LIMITS MAX	UNIT
22 to 29	Channel Off Leakage Current (Any Channel)	I_{OFF2}	-	4(e)	V_{IN} (Inhibit) = 15Vdc V_{IN} (Address Inputs) = 0Vdc V_{IN} (Channel I/O) = 0Vdc V_{IN} (Common I/O) = 15Vdc V_{DD} = 15Vdc, $V_{SS} = V_{EE}$ = 0Vdc Pins D/F — Pins C 3 to 1 — 4 to 1 3 to 2 — 4 to 2 3 to 4 — 4 to 5 3 to 5 — 4 to 6 13 to 11 — 16 to 14 13 to 12 — 16 to 15 13 to 14 — 16 to 17 13 to 15 — 16 to 19	-	100	nA
30 to 31	Channel Off Leakage Current (All Channels)	I_{OFF3}	-	4(f)	V_{IN} (Inhibit) = 15Vdc V_{IN} (Address Inputs) = 0Vdc V_{IN} (All Channel I/Os) = 0Vdc V_{IN} (Common I/O) = 15Vdc V_{DD} = 15Vdc, $V_{SS} = V_{EE}$ = 0Vdc Pins D/F — Pins C 3 to 1 — 4 to 1 3 to 2 — 4 to 2 3 to 4 — 4 to 5 3 to 5 — 4 to 6 13 to 11 — 16 to 14 13 to 12 — 16 to 15 13 to 14 — 16 to 17 13 to 15 — 16 to 19	-	100	nA
32 to 33	Channel Off Leakage Current (All Channels)	I_{OFF4}	-	4(f)	V_{IN} (Inhibit) = 15Vdc V_{IN} (Address Inputs) = 0Vdc V_{IN} (All Channel I/Os) = 15Vdc V_{IN} (Common I/O) = 0Vdc V_{DD} = 15Vdc, $V_{SS} = V_{EE}$ = 0Vdc Pins D/F — Pins C 1 to 3 — 1 to 4 2 to 3 — 2 to 4 4 to 3 — 5 to 4 5 to 3 — 6 to 4 11 to 13 — 14 to 16 12 to 13 — 15 to 16 14 to 13 — 17 to 16 15 to 13 — 19 to 16	-	-100	nA

NOTES: See Page 25.

TABLE 2 - ELECTRICAL MEASUREMENTS AT ROOM TEMPERATURE - d.c. PARAMETERS (CONT'D)

NO.	CHARACTERISTICS	SYMBOL	TEST METHOD MIL-STD 883	TEST FIG.	TEST CONDITIONS (PINS UNDER TEST D/F = DIP AND FP C = CCP)	LIMITS MIN	LIMITS MAX	UNIT
34 to 145	Channel On Resistance	R_{ON1}	-	4(g)	V_{IN} (Inhibit) = 0Vdc V_{IN} (Address Inputs): V_{IL} = 0Vdc, V_{IH} = 5Vdc I_{IN} = 100µAdc, R_L = 10kΩ Channel Input Conditions: Test Table Figure 4(g)(i). V_{DD} = 5Vdc, V_{SS} = V_{EE} = 0Vdc Note 4 Pins D/F — Pins C 3 to 1 — 4 to 1 3 to 2 — 4 to 2 3 to 4 — 4 to 5 3 to 5 — 4 to 6 13 to 11 — 16 to 14 13 to 12 — 16 to 15 13 to 14 — 16 to 17 13 to 15 — 16 to 19 1 to 3 — 1 to 4 2 to 3 — 2 to 4 4 to 3 — 5 to 4 5 to 3 — 6 to 4 11 to 13 — 14 to 16 12 to 13 — 15 to 16 14 to 13 — 17 to 16 15 to 13 — 19 to 16	-	1050	Ω
146 to 273	Channel On Resistance	R_{ON2}	-	4(g)	V_{IN} (Inhibit) = 0Vdc V_{IN} (Address Inputs): V_{IL} = 0Vdc, V_{IH} = 15Vdc I_{IN} = 100µAdc, R_L = 10kΩ Channel Input Conditions: Test Table Figure 4(g)(i). V_{DD} = 15Vdc, V_{SS} = V_{EE} = 0Vdc Note 4 Pins D/F — Pins C 3 to 1 — 4 to 1 3 to 2 — 4 to 2 3 to 4 — 4 to 5 3 to 5 — 4 to 6 13 to 11 — 16 to 14 13 to 12 — 16 to 15 13 to 14 — 16 to 17 13 to 15 — 16 to 19 1 to 3 — 1 to 4 2 to 3 — 2 to 4 4 to 3 — 5 to 4 5 to 3 — 6 to 4 11 to 13 — 14 to 16 12 to 13 — 15 to 16 14 to 13 — 17 to 16 15 to 13 — 19 to 16	-	280	Ω

NOTES: See Page 25.

TABLE 2 - ELECTRICAL MEASUREMENTS AT ROOM TEMPERATURE - d.c. PARAMETERS (CONT'D)

NO.	CHARACTERISTICS	SYMBOL	TEST METHOD MIL-STD 883	TEST FIG.	TEST CONDITIONS (PINS UNDER TEST D/F = DIP AND FP C = CCP)	LIMITS MIN	LIMITS MAX	UNIT
274	Input Voltage Low Level (Noise Immunity) (Functional Test)	V_{IL1}	-	4(h)	Address and Inhibit Inputs: V_{IL} = 1.5Vdc, V_{IH} = 3.5Vdc Channel Input: V_{IL} = 0Vdc, V_{IH} = 5Vdc V_{DD} = 5Vdc, V_{SS} = V_{EE} = 0Vdc Note 5 (Pins D/F 1-2-4-5-11-12-14-15) (Pins C 1-2-5-6-14-15-17-19)	-	0.5	V
	Input Voltage High Level (Noise Immunity) (Functional Test)	V_{IH1}				4.5	-	
275	Input Voltage Low Level (Noise Immunity) (Functional Test)	V_{IL2}	-	4(h)	Address and Inhibit Inputs: V_{IL} = 4Vdc, V_{IH} = 11Vdc Channel Input: V_{IL} = 0Vdc, V_{IH} = 15Vdc V_{DD} = 15Vdc, V_{SS} = V_{EE} = 0Vdc Note 5 (Pins D/F 1-2-4-5-11-12-14-15) (Pins C 1-2-5-6-14-15-17-19)	-	1.5	V
	Input Voltage High Level (Noise Immunity) (Functional Test)	V_{IH2}				13.5	-	
276	Threshold Voltage N-Channel	V_{THN}	-	4(i)	Inhibit and V_{EE} at Ground. All Other Inputs: V_{IN} = 5Vdc V_{DD} = 5Vdc, I_{SS} = -10µA (Pin D/F 8) (Pin C 10)	-0.7	-3.0	V
277	Threshold Voltage P-Channel	V_{THP}	-	4(j)	Inhibit at Ground. All Other Inputs: V_{IN} = -5Vdc V_{SS} = V_{EE} = -5Vdc, I_{DD} = 3.5µA (Pin D/F 16) (Pin C 20)	0.7	3.0	V
278 to 280	Input Clamp Voltage (to V_{SS})	V_{IC1}	-	4(k)	I_{IN} (Under Test) = -100µA V_{DD} = Open, V_{SS} = 0Vdc All Other Pins Open (Pins D/F 6-9-10) (Pins C 7-11-12)	-	-2.0	V
281 to 283	Input ClampVoltage (to V_{DD})	V_{IC2}	-	4(l)	V_{IN} (Under Test) = 6Vdc V_{SS} = Open, R = 30kΩ; (Pins D/F 6-9-10) (Pins C 7-11-12)	3.0	-	V

NOTES: See Page 25.

TABLE 2 - ELECTRICAL MEASUREMENTS AT ROOM TEMPERATURE - a.c. PARAMETERS

NO.	CHARACTERISTICS	SYMBOL	TEST METHOD MIL-STD 883	TEST FIG.	TEST CONDITIONS (PINS UNDER TEST D/F = DIP AND FP C = CCP)	LIMITS		UNIT
						MIN	MAX	
284 to 286	Input Capacitance Address or Inhibit	C_{IN}	3012	4(m)	V_{IN} (Not Under Test) = 0Vdc V_{DD} = V_{SS} = V_{EE} = 0Vdc Note 6 (Pins D/F 6-9-10) (Pins C 7-11-12)	-	7.5	pF
287 to 294	Channel Capacitance (Input)	C_{INC}	3012	4(n)	V_{DD} = V_{SS} = V_{EE} = 0Vdc Note 6 (Pins D/F 1-2-4-5-11-12-14-15) (Pins C 1-2-5-6-14-15-17-19)	-	7.5	pF
295 to 296	Channel Capacitance (Output)	C_{OC}	3012	4(o)	V_{DD} = V_{SS} = V_{EE} = 0Vdc Note 6 (Pins D/F 3-13) (Pins C 4-16)	-	30	pF
297	Propagation Delay Channel Input to Channel Output	t_{PLH1}	3003	4(q)	V_{IN} (Under Test) = Pulse Generator V_{IL} = 0Vdc, V_{IH} = 5Vdc R_L = 200kΩ V_{DD} = 5Vdc, V_{SS} = V_{EE} = 0Vdc Note 7 Pins D/F: 13 to 12 Pins C: 16 to 15	-	40	ns
298	Propagation Delay Address to Signal OUT (Channel turning ON)	t_{PLH2}	3003	4(p)	V_{IN} (Under Test) = Pulse Generator V_{IL} = 0Vdc, V_{IH} = 5Vdc R_L = 10kΩ V_{DD} = 5Vdc, V_{SS} = V_{EE} = 0Vdc Note 7 Pins D/F: 10 to 3 Pins C: 12 to 4	-	720	ns
299	Propagation Delay Inhibit to Signal OUT (Channel turning ON)	t_{PLH3}	3003	4(p)	V_{IN} (Under Test) = Pulse Generator V_{IL} = 0Vdc, V_{IH} = 5Vdc R_L = 10kΩ V_{DD} = 5Vdc, V_{SS} = V_{EE} = 0Vdc Note 7 Pins D/F: 6 to 3 Pins C: 7 to 4	-	400	ns

NOTES: See Page 25.

TABLE 2 - ELECTRICAL MEASUREMENTS AT ROOM TEMPERATURE - a.c. PARAMETERS (CONT'D)

NO.	CHARACTERISTICS	SYMBOL	TEST METHOD MIL-STD 883	TEST FIG.	TEST CONDITIONS (PINS UNDER TEST D/F = DIP AND FP C = CCP)	LIMITS		UNIT
						MIN	MAX	
300	Propagation Delay Channel Input to Channel Output	t_{PHL1}	3003	4(q)	V_{IN} (Under Test) = Pulse Generator V_{IL} = 0Vdc, V_{IH} = 5Vdc R_L = 200kΩ V_{DD} = 5Vdc, V_{SS} = V_{EE} = 0Vdc Note 7 Pins D/F: 13 to 12 Pins C: 16 to 15	-	40	ns
301	Propagation Delay Address to Signal OUT (Channel turning OFF)	t_{PHL2}	3003	4(p)	V_{IN} (Under Test) = Pulse Generator V_{IL} = 0Vdc, V_{IH} = 5Vdc, R_L = 300Ω V_{DD} = 5Vdc, V_{SS} = V_{EE} = 0Vdc Note 7 Pins D/F: 10 to 3 Pins C: 12 to 4	-	720	ns
302	Propagation Delay Inhibit to Signal OUT (Channel turning OFF)	t_{PHL3}	3003	4(p)	V_{IN} (Under Test) = Pulse Generator V_{IL} = 0Vdc, V_{IH} = 5Vdc R_L = 300Ω V_{DD} = 5Vdc, V_{SS} = V_{EE} = 0Vdc Note 7 Pins D/F: 6 to 3 Pins C: 7 to 4	-	400	ns

NOTES

1. GO-NO-GO Test, each pattern of Test Table 4(a).
   $V_{OH} \geq V_{DD}$ - 0.5Vdc $V_{OL} \leq$ 0.5Vdc
2. Maximum time to output comparator strobe 300µsec.
3. Measure each value of I_{DD} for the input conditions given in Table 4(b).
4. For characterisation during qualification, the incremental method or the method shown in Figure 4(g)(ii), which incorporates a plotter, shall apply. For procurement, the Orderer may accept that the devices are tested go-no-go to the maximum limits of Table 2. In the case that go-no-go testing is performed, it is necessary that at least one discrete value shall be measured and recorded in order that drift values may be applied. Figure 4(g)(iii) shall be used for the discrete value measurement.
5. This is performed as a Functional Test in which extreme V_{IN} conditions are applied and channel selection is monitored.
6. Measurement performed on a sample basis, LTPD 7 or less, with a Capacitance Bridge connected between each input or output under test and V_{SS}, only for Lots where LAT Level 2 is to be performed. (For LTPD sampling plan, see Annexe I of ESA/SCC 9000).
7. Measurement performed on a sample basis LTPD 7, or less (see Annexe I of ESA/SCC 9000).

TABLE 3(a) - ELECTRICAL MEASUREMENTS AT HIGH TEMPERATURE, +125(+0-5) °C

NO.	CHARACTERISTICS	SYMBOL	TEST METHOD MIL-STD 883	TEST FIG.	TEST CONDITIONS (PINS UNDER TEST D/F = DIP AND FP C = CCP)	LIMITS		UNIT
						MIN	MAX	
1	Functional Test	-	-	4(a)	Verify Truth Table without Load. V_{DD} = 3Vdc, V_{SS} = V_{EE} = 0Vdc Notes 1 and 2	-	-	-
2	Functional Test	-	-	4(a)	Verify Truth Table without Load. V_{DD} = 15Vdc, V_{SS} = V_{EE} = 0Vdc Notes 1 and 2	-	-	-
3 to 7	Quiescent Current	I_{DD}	3005	4(b)	V_{IL} = 0Vdc, V_{IH} = 15Vdc V_{DD} = 15Vdc, V_{SS} = V_{EE} = 0Vdc Note 3 (Pin D/F 16) (Pin C 20)	-	30	µA
8 to 10	Input Current Low Level Address or Inhibit	I_{IL}	3009	4(c)	V_{IN} (Under Test) = 0Vdc V_{IN} (Other Inputs) = 15Vdc V_{DD} = 15Vdc, V_{SS} = V_{EE} = 0Vdc (Pins D/F 6-9-10) (Pins C 7-11-12)	-	-100	nA
11 to 13	Input Current High Level Address or Inhibit	I_{IH}	3010	4(d)	V_{IN} (Under Test) = 15Vdc V_{IN} (Other Inputs) = 0Vdc V_{DD} = 15Vdc, V_{SS} = V_{EE} = 0Vdc (Pins D/F 6-9-10) (Pins C 7-11-12)	-	100	nA
14 to 21	Channel Off Leakage Current (Any Channel)	I_{OFF1}	-	4(e)	V_{IN} (Inhibit) = 15Vdc V_{IN} (Address Inputs) = 0Vdc V_{IN} (Channel I/O) = 15Vdc V_{IN} (Common I/O) = 0Vdc V_{DD} = 15Vdc, V_{SS} = V_{EE} = 0Vdc Pins D/F — Pins C 1 to 3 — 1 to 4 2 to 3 — 2 to 4 4 to 3 — 5 to 4 5 to 3 — 6 to 4 11 to 13 — 14 to 16 12 to 13 — 15 to 16 14 to 13 — 17 to 16 15 to 13 — 19 to 16	-	-1.0	µA

NOTES: See Page 25.

TABLE 3(a) - ELECTRICAL MEASUREMENTS AT HIGH TEMPERATURE, + 125(+ 0-5) °C (CONT'D)

NO.	CHARACTERISTICS	SYMBOL	TEST METHOD MIL-STD 883	TEST FIG.	TEST CONDITIONS (PINS UNDER TEST D/F = DIP AND FP C = CCP)	LIMITS MIN	LIMITS MAX	UNIT
22 to 29	Channel Off Leakage Current (Any Channel)	I_{OFF2}	-	4(e)	V_{IN} (Inhibit) = 15Vdc V_{IN} (Address Inputs) = 0Vdc V_{IN} (Channel I/O) = 0Vdc V_{IN} (Common I/O) = 15Vdc V_{DD} = 15Vdc, $V_{SS} = V_{EE}$ = 0Vdc Pins D/F — Pins C 3 to 1 — 4 to 1 3 to 2 — 4 to 2 3 to 4 — 4 to 5 3 to 5 — 4 to 6 13 to 11 — 16 to 14 13 to 12 — 16 to 15 13 to 14 — 16 to 17 13 to 15 — 16 to 19	-	1.0	µA
30 to 31	Channel Off Leakage Current (All Channels)	I_{OFF3}	-	4(f)	V_{IN} (Inhibit) = 15Vdc V_{IN} (Address Inputs) = 0Vdc V_{IN} (All Channel I/Os) = 0Vdc V_{IN} (Common I/O) = 15Vdc V_{DD} = 15Vdc, $V_{SS} = V_{EE}$ = 0Vdc Pins D/F — Pins C 3 to 1 — 4 to 1 3 to 2 — 4 to 2 3 to 4 — 4 to 5 3 to 5 — 4 to 6 13 to 11 — 16 to 14 13 to 12 — 16 to 15 13 to 14 — 16 to 17 13 to 15 — 16 to 19	-	1.0	µA
32 to 33	Channel Off Leakage Current (All Channels)	I_{OFF4}	-	4(f)	V_{IN} (Inhibit) = 15Vdc V_{IN} (Address Inputs) = 0Vdc V_{IN} (All Channel I/Os) = 15Vdc V_{IN} (Common I/O) = 0Vdc V_{DD} = 15Vdc, $V_{SS} = V_{EE}$ = 0Vdc Pins D/F — Pins C 1 to 3 — 1 to 4 2 to 3 — 2 to 4 4 to 3 — 5 to 4 5 to 3 — 6 to 4 11 to 13 — 14 to 16 12 to 13 — 15 to 16 14 to 13 — 17 to 16 15 to 13 — 19 to 16	-	-1.0	µA

NOTES: See Page 25.

TABLE 3(a) - ELECTRICAL MEASUREMENTS AT HIGH TEMPERATURE, + 125(+ 0-5) °C (CONT'D)

NO.	CHARACTERISTICS	SYMBOL	TEST METHOD MIL-STD 883	TEST FIG.	TEST CONDITIONS (PINS UNDER TEST D/F = DIP AND FP C = CCP)	LIMITS MIN	LIMITS MAX	UNIT
34 to 145	Channel On Resistance	R_{ON1}	-	4(g)	V_{IN} (Inhibit) = 0Vdc V_{IN} (Address Inputs): V_{IL} = 0Vdc, V_{IH} = 5Vdc I_{IN} = 100μAdc, R_L = 10kΩ Channel Input Conditions: Test Table Figure 4(g)(i). V_{DD} = 5Vdc, V_{SS} = V_{EE} = 0Vdc Note 4 Pins D/F — Pins C 3 to 1 — 4 to 1 3 to 2 — 4 to 2 3 to 4 — 4 to 5 3 to 5 — 4 to 6 13 to 11 — 16 to 14 13 to 12 — 16 to 15 13 to 14 — 16 to 17 13 to 15 — 16 to 19 1 to 3 — 1 to 4 2 to 3 — 2 to 4 4 to 3 — 5 to 4 5 to 3 — 6 to 4 11 to 13 — 14 to 16 12 to 13 — 15 to 16 14 to 13 — 17 to 16 15 to 13 — 19 to 16	-	1200	Ω
146 to 273	Channel On Resistance	R_{ON2}	-	4(g)	V_{IN} (Inhibit) = 0Vdc V_{IN} (Address Inputs): V_{IL} = 0Vdc, V_{IH} = 15Vdc I_{IN} = 100μAdc, R_L = 10kΩ Channel Input Conditions: Test Table Figure 4(g)(i). V_{DD} = 15Vdc, V_{SS} = V_{EE} = 0Vdc Note 4 Pins D/F — Pins C 3 to 1 — 4 to 1 3 to 2 — 4 to 2 3 to 4 — 4 to 5 3 to 5 — 4 to 6 13 to 11 — 16 to 14 13 to 12 — 16 to 15 13 to 14 — 16 to 17 13 to 15 — 16 to 19 1 to 3 — 1 to 4 2 to 3 — 2 to 4 4 to 3 — 5 to 4 5 to 3 — 6 to 4 11 to 13 — 14 to 16 12 to 13 — 15 to 16 14 to 13 — 17 to 16 15 to 13 — 19 to 16	-	400	Ω

NOTES: See Page 25.

TABLE 3(a) - ELECTRICAL MEASUREMENTS AT HIGH TEMPERATURE, + 125(+ 0-5) °C (CONT'D)

NO.	CHARACTERISTICS	SYMBOL	TEST METHOD MIL-STD 883	TEST FIG.	TEST CONDITIONS (PINS UNDER TEST D/F = DIP AND FP C = CCP)	LIMITS MIN	LIMITS MAX	UNIT
274	Input Voltage Low Level (Noise Immunity) (Functional Test)	V_{IL1}	-	4(h)	Address and Inhibit Inputs: V_{IL} = 1.5Vdc, V_{IH} = 3.5Vdc Channel Input: V_{IL} = 0Vdc, V_{IH} = 5Vdc V_{DD} = 5Vdc, V_{SS} = V_{EE} = 0Vdc Note 5 (Pins D/F 1-2-4-5-11-12-14-15) (Pins C 1-2-5-6-14-15-17-19)	-	0.5	V
	Input Voltage High Level (Noise Immunity) (Functional Test)	V_{IH1}				4.5	-	
275	Input Voltage Low Level (Noise Immunity) (Functional Test)	V_{IL2}	-	4(h)	Address and Inhibit Inputs: V_{IL} = 4Vdc, V_{IH} = 11Vdc Channel Input: V_{IL} = 0Vdc, V_{IH} = 15Vdc V_{DD} = 15Vdc, V_{SS} = V_{EE} = 0Vdc Note 5 (Pins D/F 1-2-4-5-11-12-14-15) (Pins C 1-2-5-6-14-15-17-19)	-	1.5	V
	Input Voltage High Level (Noise Immunity) (Functional Test)	V_{IH2}				13.5	-	
276	Threshold Voltage N-Channel	V_{THN}	-	4(i)	Inhibit and V_{EE} at Ground. All Other Inputs: V_{IN} = 5Vdc V_{DD} = 5Vdc, I_{SS} = -10µA (Pin D/F 8) (Pin C 10)	-0.3	-3.5	V
277	Threshold Voltage P-Channel	V_{THP}	-	4(j)	Inhibit at Ground. All Other Inputs: V_{IN} = -5Vdc V_{SS} = V_{EE} = -5Vdc, I_{DD} = 3.5µA (Pin D/F 16) (Pin C 20)	0.3	3.5	V

NOTES: See Page 25.

TABLE 3(b) - ELECTRICAL MEASUREMENTS AT LOW TEMPERATURE, -55(+5-0) °C

NO.	CHARACTERISTICS	SYMBOL	TEST METHOD MIL-STD 883	TEST FIG.	TEST CONDITIONS (PINS UNDER TEST D/F = DIP AND FP C = CCP)	LIMITS		UNIT
						MIN	MAX	
1	Functional Test	-	-	4(a)	Verify Truth Table without Load. V_{DD} = 3Vdc, V_{SS} = V_{EE} = 0Vdc Notes 1 and 2	-	-	-
2	Functional Test	-	-	4(a)	Verify Truth Table without Load. V_{DD} = 15Vdc, V_{SS} = V_{EE} = 0Vdc Notes 1 and 2	-	-	-
3 to 7	Quiescent Current	I_{DD}	3005	4(b)	V_{IL} = 0Vdc, V_{IH} = 15Vdc V_{DD} = 15Vdc, V_{SS} = V_{EE} = 0Vdc Note 3 (Pin D/F 16) (Pin C 20)	-	1.0	µA
8 to 10	Input Current Low Level Address or Inhibit	I_{IL}	3009	4(c)	V_{IN} (Under Test) = 0Vdc V_{IN} (Other Inputs) = 15Vdc V_{DD} = 15Vdc, V_{SS} = V_{EE} = 0Vdc (Pins D/F 6-9-10) (Pins C 7-11-12)	-	-50	nA
11 to 13	Input Current High Level Address or Inhibit	I_{IH}	3010	4(d)	V_{IN} (Under Test) = 15Vdc V_{IN} (Other Inputs) = 0Vdc V_{DD} = 15Vdc, V_{SS} = V_{EE} = 0Vdc (Pins D/F 6-9-10) (Pins C 7-11-12)	-	50	nA
14 to 21	Channel Off Leakage Current (Any Channel)	I_{OFF1}	-	4(e)	V_{IN} (Inhibit) = 15Vdc V_{IN} (Address Inputs) = 0Vdc V_{IN} (Channel I/O) = 15Vdc V_{IN} (Common I/O) = 0Vdc V_{DD} = 15Vdc, V_{SS} = V_{EE} = 0Vdc Pins D/F — Pins C 1 to 3 — 1 to 4 2 to 3 — 2 to 4 4 to 3 — 5 to 4 5 to 3 — 6 to 4 11 to 13 — 14 to 16 12 to 13 — 15 to 16 14 to 13 — 17 to 16 15 to 13 — 19 to 16	-	-100	nA

NOTES: See Page 25.

TABLE 3(b) - ELECTRICAL MEASUREMENTS AT LOW TEMPERATURE, -55(+5-0) °C (CONT'D)

NO.	CHARACTERISTICS	SYMBOL	TEST METHOD MIL-STD 883	TEST FIG.	TEST CONDITIONS (PINS UNDER TEST D/F = DIP AND FP C = CCP)	LIMITS		UNIT
						MIN	MAX	
22 to 29	Channel Off Leakage Current (Any Channel)	I_{OFF2}	-	4(e)	V_{IN} (Inhibit) = 15Vdc V_{IN} (Address Inputs) = 0Vdc V_{IN} (Channel I/O) = 0Vdc V_{IN} (Common I/O) = 15Vdc V_{DD} = 15Vdc, $V_{SS} = V_{EE}$ = 0Vdc Pins D/F — Pins C 3 to 1 — 4 to 1 3 to 2 — 4 to 2 3 to 4 — 4 to 5 3 to 5 — 4 to 6 13 to 11 — 16 to 14 13 to 12 — 16 to 15 13 to 14 — 16 to 17 13 to 15 — 16 to 19	-	100	nA
30 to 31	Channel Off Leakage Current (All Channels)	I_{OFF3}	-	4(f)	V_{IN} (Inhibit) = 15Vdc V_{IN} (Address Inputs) = 0Vdc V_{IN} (All Channel I/Os) = 0Vdc V_{IN} (Common I/O) = 15Vdc V_{DD} = 15Vdc, $V_{SS} = V_{EE}$ = 0Vdc Pins D/F — Pins C 3 to 1 — 4 to 1 3 to 2 — 4 to 2 3 to 4 — 4 to 5 3 to 5 — 4 to 6 13 to 11 — 16 to 14 13 to 12 — 16 to 15 13 to 14 — 16 to 17 13 to 15 — 16 to 19	-	100	nA
32 to 33	Channel Off Leakage Current (All Channels)	I_{OFF4}	-	4(f)	V_{IN} (Inhibit) = 15Vdc V_{IN} (Address Inputs) = 0Vdc V_{IN} (All Channel I/Os) = 15Vdc V_{IN} (Common I/O) = 0Vdc V_{DD} = 15Vdc, $V_{SS} = V_{EE}$ = 0Vdc Pins D/F — Pins C 1 to 3 — 1 to 4 2 to 3 — 2 to 4 4 to 3 — 5 to 4 5 to 3 — 6 to 4 11 to 13 — 14 to 16 12 to 13 — 15 to 16 14 to 13 — 17 to 16 15 to 13 — 19 to 16	-	-100	nA

NOTES: See Page 25.

TABLE 3(b) - ELECTRICAL MEASUREMENTS AT LOW TEMPERATURE, -55(+5-0) °C (CONT'D)

NO.	CHARACTERISTICS	SYMBOL	TEST METHOD MIL-STD 883	TEST FIG.	TEST CONDITIONS (PINS UNDER TEST D/F = DIP AND FP C = CCP)	LIMITS MIN	LIMITS MAX	UNIT
34 to 145	Channel On Resistance	R_{ON1}	-	4(g)	V_{IN} (Inhibit) = 0Vdc V_{IN} (Address Inputs): V_{IL} = 0Vdc, V_{IH} = 5Vdc I_{IN} = 100µAdc, R_L = 10kΩ Channel Input Conditions: Test Table Figure 4(g)(i). V_{DD} = 5Vdc, V_{SS} = V_{EE} = 0Vdc Note 4 Pins D/F — Pins C 3 to 1 — 4 to 1 3 to 2 — 4 to 2 3 to 4 — 4 to 5 3 to 5 — 4 to 6 13 to 11 — 16 to 14 13 to 12 — 16 to 15 13 to 14 — 16 to 17 13 to 15 — 16 to 19 1 to 3 — 1 to 4 2 to 3 — 2 to 4 4 to 3 — 5 to 4 5 to 3 — 6 to 4 11 to 13 — 14 to 16 12 to 13 — 15 to 16 14 to 13 — 17 to 16 15 to 13 — 19 to 16	-	880	Ω
146 to 273	Channel On Resistance	R_{ON2}	-	4(g)	V_{IN} (Inhibit) = 0Vdc V_{IN} (Address Inputs): V_{IL} = 0Vdc, V_{IH} = 15Vdc I_{IN} = 100µAdc, R_L = 10kΩ Channel Input Conditions: Test Table Figure 4(g)(i). V_{DD} = 15Vdc, V_{SS} = V_{EE} = 0Vdc Note 4 Pins D/F — Pins C 3 to 1 — 4 to 1 3 to 2 — 4 to 2 3 to 4 — 4 to 5 3 to 5 — 4 to 6 13 to 11 — 16 to 14 13 to 12 — 16 to 15 13 to 14 — 16 to 17 13 to 15 — 16 to 19 1 to 3 — 1 to 4 2 to 3 — 2 to 4 4 to 3 — 5 to 4 5 to 3 — 6 to 4 11 to 13 — 14 to 16 12 to 13 — 15 to 16 14 to 13 — 17 to 16 15 to 13 — 19 to 16	-	220	Ω

NOTES: See Page 25.

TABLE 3(b) - ELECTRICAL MEASUREMENTS AT LOW TEMPERATURE, -55(+5-0) °C (CONT'D)

NO.	CHARACTERISTICS	SYMBOL	TEST METHOD MIL-STD 883	TEST FIG.	TEST CONDITIONS (PINS UNDER TEST D/F = DIP AND FP C = CCP)	LIMITS MIN	LIMITS MAX	UNIT
274	Input Voltage Low Level (Noise Immunity) (Functional Test)	V_{IL1}	-	4(h)	Address and Inhibit Inputs: V_{IL} = 1.5Vdc, V_{IH} = 3.5Vdc Channel Input: V_{IL} = 0Vdc, V_{IH} = 5Vdc V_{DD} = 5Vdc, V_{SS} = V_{EE} = 0Vdc Note 5 (Pins D/F 1-2-4-5-11-12-14-15) (Pins C 1-2-5-6-14-15-17-19)	-	0.5	V
	Input Voltage High Level (Noise Immunity) (Functional Test)	V_{IH1}				4.5	-	
275	Input Voltage Low Level (Noise Immunity) (Functional Test)	V_{IL2}	-	4(h)	Address and Inhibit Inputs: V_{IL} = 4Vdc, V_{IH} = 11Vdc Channel Input: V_{IL} = 0Vdc, V_{IH} = 15Vdc V_{DD} = 15Vdc, V_{SS} = V_{EE} = 0Vdc Note 5 (Pins D/F 1-2-4-5-11-12-14-15) (Pins C 1-2-5-6-14-15-17-19)	-	1.5	V
	Input Voltage High Level (Noise Immunity) (Functional Test)	V_{IH2}				13.5	-	
276	Threshold Voltage N-Channel	V_{THN}	-	4(i)	Inhibit and V_{EE} at Ground. All Other Inputs: V_{IN} = 5Vdc V_{DD} = 5Vdc, I_{SS} = -10µA (Pin D/F 8) (Pin C 10)	-0.7	-3.5	V
277	Threshold Voltage P-Channel	V_{THP}	-	4(j)	Inhibit at Ground. All Other Inputs: V_{IN} = -5Vdc V_{SS} = V_{EE} = -5Vdc, I_{DD} = 3.5µA (Pin D/F 16) (Pin C 20)	0.7	3.5	V

NOTES: See Page 25.

FIGURE 4 - CIRCUITS FOR ELECTRICAL MEASUREMENTS

FIGURE 4(a) - FUNCTIONAL TEST TABLE

PATTERN NO.	PIN NUMBERS													D.C. SUPPLY		
	1	2	3	4	5	6	9	10	11	12	13	14	15	7	8	16
0	0	1	0	1	1	0	0	0	1	0	0	1	1	V_{EE}	V_{SS}	V_{DD}
1	1	0	1	0	0	0	0	0	0	1	1	0	0	↓	↓	↓
2	1	1	0	1	0	0	0	1	1	1	0	0	1			
3	0	0	1	0	1	0	0	1	0	0	1	1	0			
4	1	0	0	1	1	0	1	0	1	1	0	1	0			
5	0	1	1	0	0	0	1	0	0	0	1	0	1			
6	1	1	0	0	1	0	1	1	0	1	0	1	1			
7	0	0	1	1	0	0	1	1	1	0	1	0	0			
8	0	0	1	0	0	1	0	0	0	0	1	0	0			
9	0	0	1	0	0	1	0	1	0	0	1	0	0			
10	0	0	1	0	0	1	1	0	0	0	1	0	0			
11	0	0	1	0	0	1	1	1	0	0	1	0	0			
12	1	1	0	1	1	1	0	0	1	1	0	1	1			
13	1	1	0	1	1	1	0	1	1	1	0	1	1			
14	1	1	0	1	1	1	1	0	1	1	0	1	1			
15	1	1	0	1	1	1	1	1	1	1	0	1	1			

NOTES

1. Figure 4(a) illustrates one series of test patterns. Any other pattern series must be agreed with the Qualifying Space Agency and shall be included as an Appendix.
2. Logic Level Definitions: 1 = V_{IH} = V_{DD}, 0 = V_{IL} = V_{SS}.
3. Test set-up:
   - Common switch output connected to V_{DD} supply.
   - Switch inputs connected individually through 33kΩ to the Digital Comparator and through 100kΩ at V_{DD} = 3V.

FIGURE 4(b) - QUIESCENT CURRENT TEST TABLE

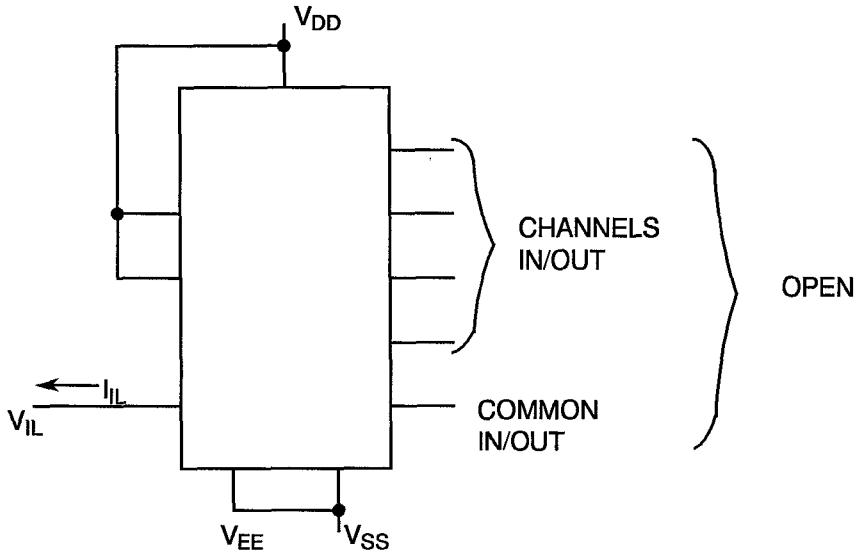
PATTERN NO.	PIN NUMBERS															D.C. SUPPLY		
	INPUTS													OUTPUTS				
	6	9	10	1	2	4	5	11	12	13	14	15	3	13	7	8	16
1	0	0	0	1	1	1	1	1	1	1	1	1	X	X	V_{EE}	V_{SS}	V_{DD}
2	0	0	1	1	1	1	1	1	1	1	1	1	X	X	↓	↓	↓
3	0	1	0	0	0	0	0	0	0	0	0	0	X	X			
4	0	1	1	0	0	0	0	0	0	0	0	0	X	X			
5	1	0	0	1	1	1	1	1	1	1	1	1	X	X			

NOTES

1. Figure 4(b) illustrates one series of Test Patterns. Any other pattern series must be agreed with the Qualifying Space Agency and shall be included as an appendix.
2. Logic Level Definitions: 1 = V_{IH} = V_{DD}, 0 = V_{IL} = V_{SS}, X = Don't Care.

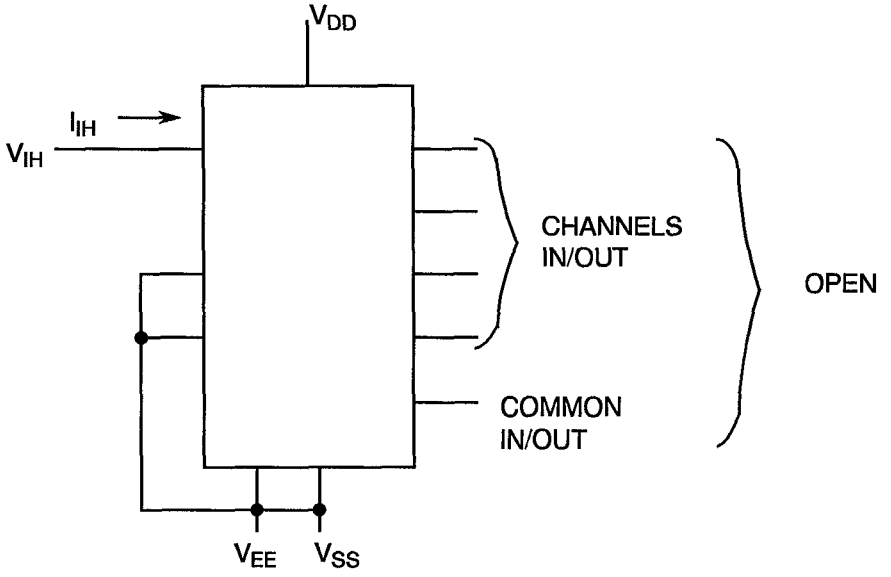
FIGURE 4 - CIRCUITS FOR ELECTRICAL MEASUREMENTS (CONTINUED)

FIGURE 4(c) - INPUT CURRENT LOW LEVEL



NOTES
1. Each input to be tested separately.

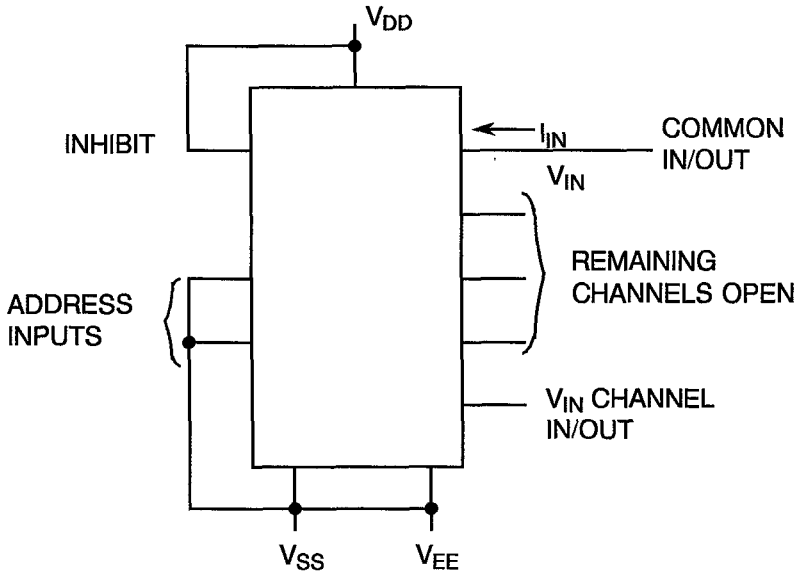
FIGURE 4(d) - INPUT CURRENT HIGH LEVEL



NOTES
1. Each input to be tested separately.

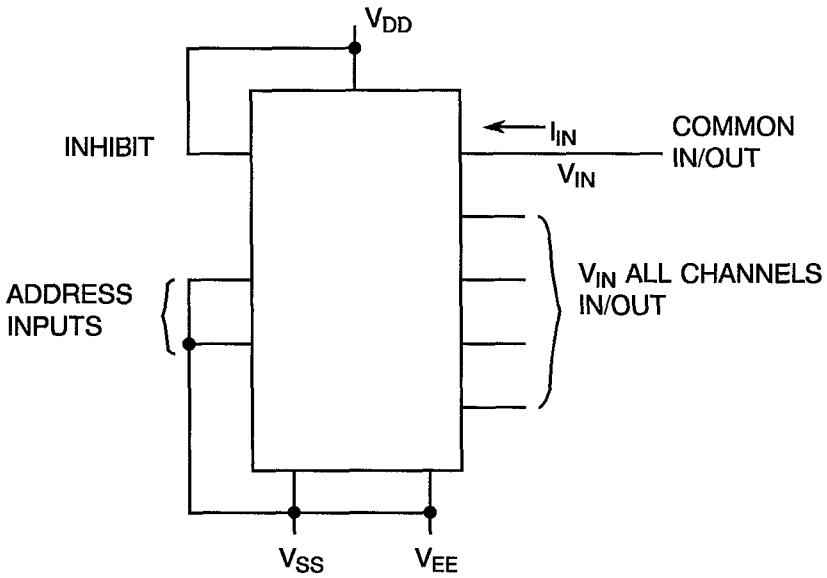
FIGURE 4 - CIRCUITS FOR ELECTRICAL MEASUREMENTS (CONTINUED)

FIGURE 4(e) - CHANNEL OFF LEAKAGE CURRENT



NOTES
1. Each output to be tested separately.

FIGURE 4(f) - CHANNEL TOTAL OFF LEAKAGE CURRENT



NOTES
1. Each output to be tested separately.

FIGURE 4 - CIRCUITS FOR ELECTRICAL MEASUREMENTS

FIGURE 4(g)(i) - TEST TABLE FOR CHANNEL ON RESISTANCE

PATTERN NO.	PIN NUMBERS															
	INPUTS											OUTPUTS		D.C. SUPPLY		
	6	9	10	12	1	14	5	15	2	11	4	13	3	7	8	16
1	0	0	0	(2)	0	0	0	0	0	0	0	X		V_{EE}	V_{SS}	V_{DD}
2	0	0	0	0	(2)	0	0	0	0	0	0		X	↓	↓	↓
3	0	0	1	0	0	(2)	0	0	0	0	0	X				
4	0	0	1	0	0	0	(2)	0	0	0	0		X			
5	0	1	0	0	0	0	0	(2)	0	0	0	X				
6	0	1	0	0	0	0	0	0	(2)	0	0		X			
7	0	1	1	0	0	0	0	0	0	(2)	0	X				
8	0	1	1	0	0	0	0	0	0	0	(2)		X			

NOTES

1. Logic Level Definitions: 1 = V_{IH} = V_{DD}, 0 = V_{IL} = V_{SS}.

2. The following notes apply:-

   (i) V_{IN} (FORCED) — 0 — T.G. — 0 — V_{OUT}

   (ii) R_{ON} 5V: V_{IN} = 1.5V, 1.9V, 2.3V, 2.7V, 3.3V, 3.7V, 4.1V
   V_{OUT} = V_{IN} - 200mV

   (iii) R_{ON} 15V: V_{IN} = 1.5V, 1.9V, 2.3V, 2.7V, 13.3V, 13.7V, 14.1V, 14.5V
   V_{OUT} = V_{IN} - 200mV

FIGURE 4 - CIRCUITS FOR ELECTRICAL MEASUREMENTS (CONTINUED)

FIGURE 4(g)(ii) - CHANNEL ON RESISTANCE

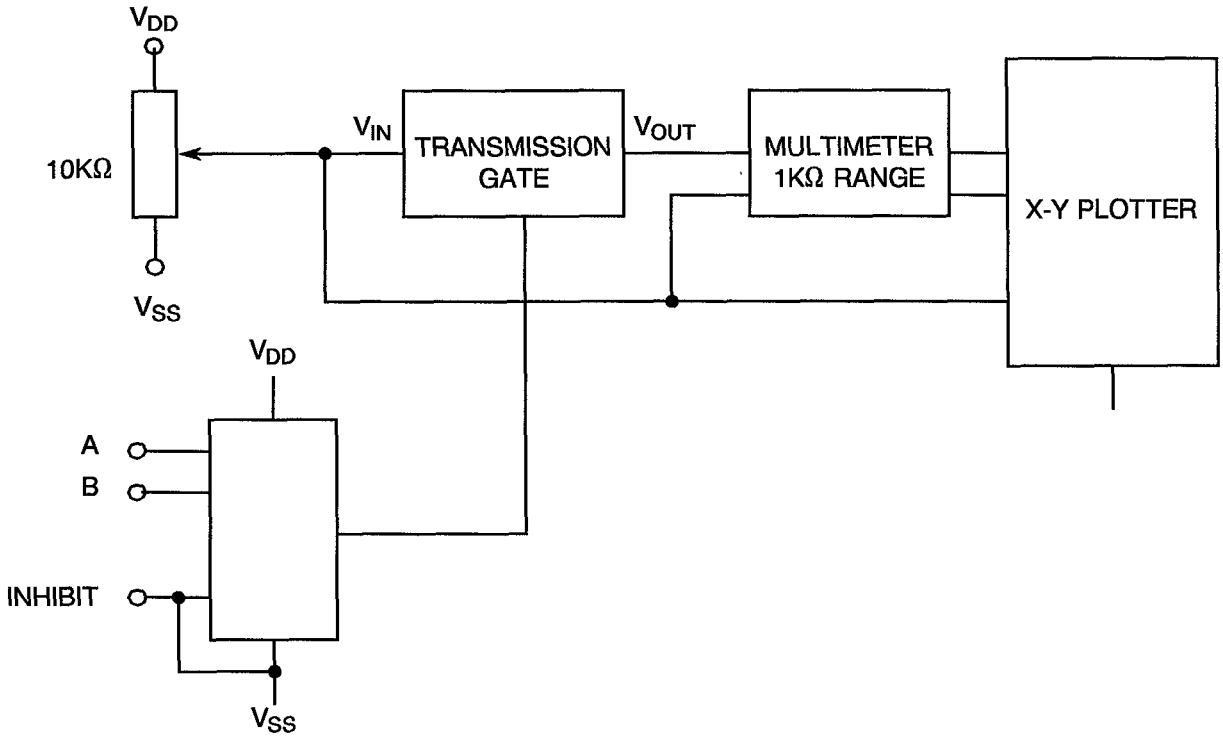


FIGURE 4(g)(iii) - CHANNEL ON RESISTANCE

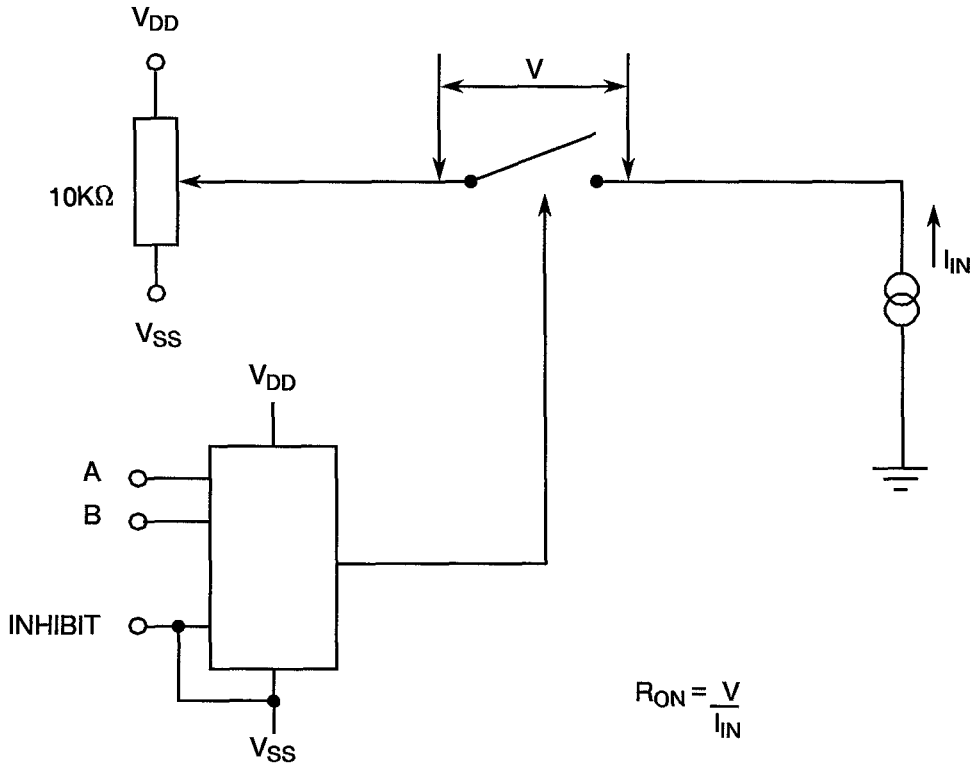
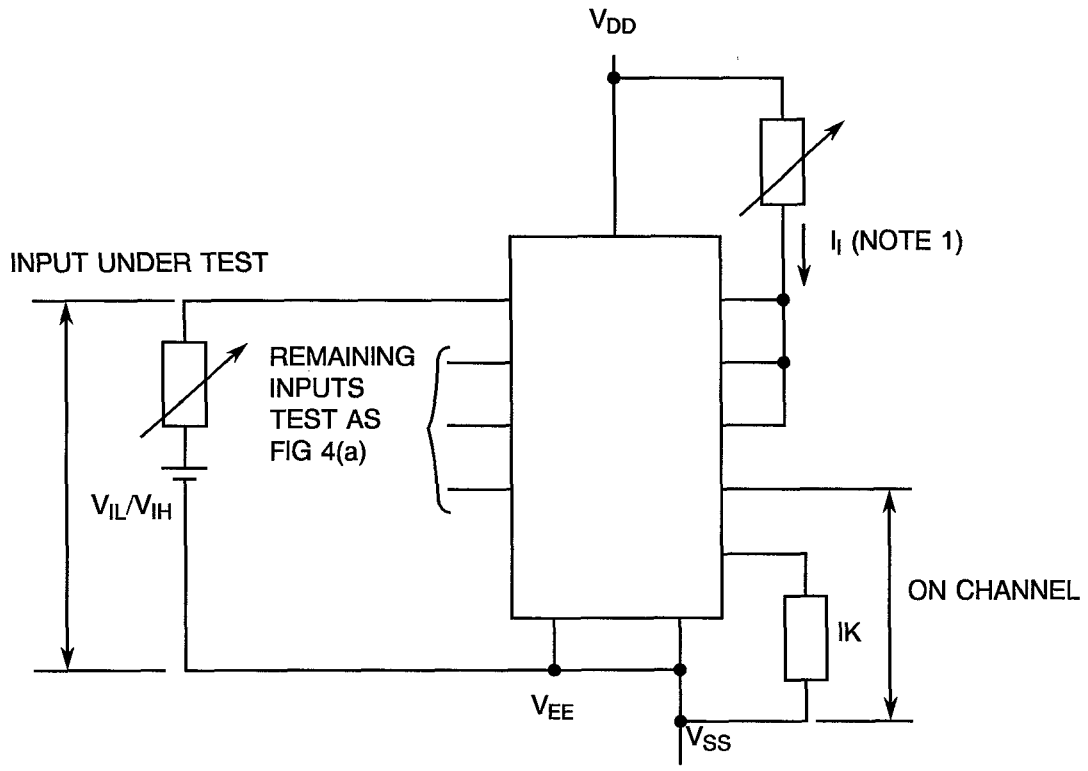


FIGURE 4 - CIRCUITS FOR ELECTRICAL MEASUREMENTS (CONTINUED)

FIGURE 4(h) - INPUT VOLTAGE HIGH AND LOW LEVEL



NOTES:

1. I_I < 2μA for all OFF Channels

FIGURE 4 - CIRCUITS FOR ELECTRICAL MEASUREMENTS (CONTINUED)

FIGURE 4(i) - THRESHOLD VOLTAGE N-CHANNEL

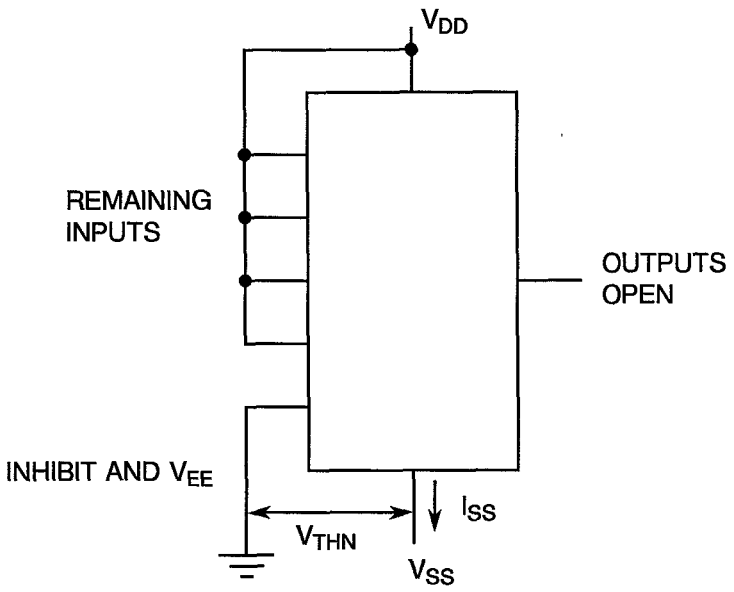


FIGURE 4(j) - THRESHOLD VOLTAGE P-CHANNEL

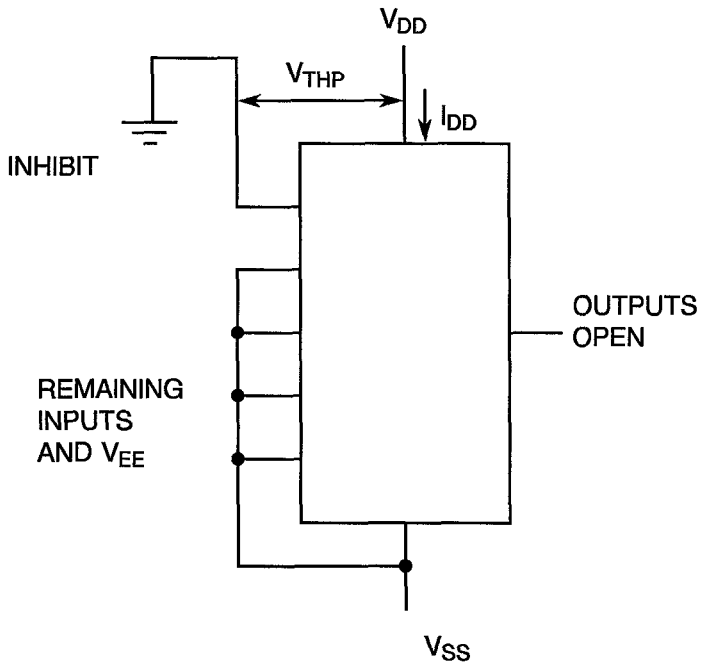
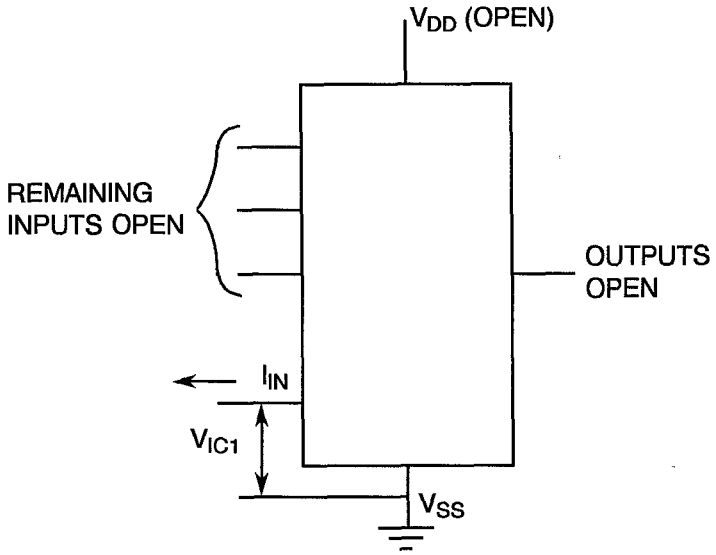


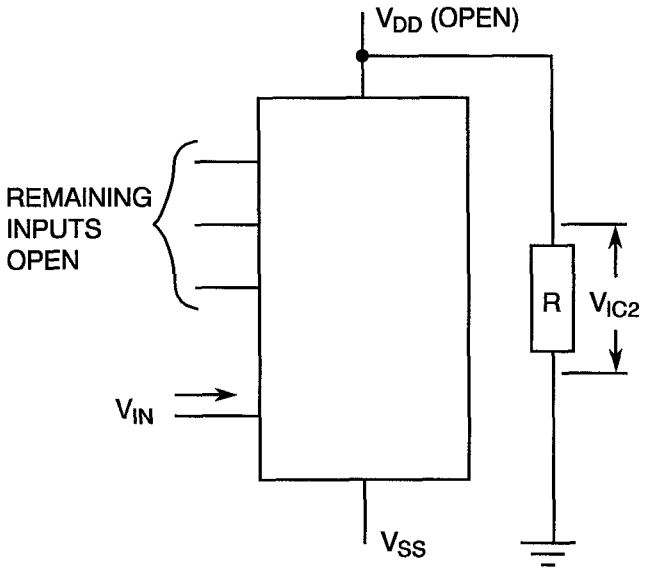
FIGURE 4 - CIRCUITS FOR ELECTRICAL MEASUREMENTS (CONTINUED)

FIGURE 4(k) - INPUT CLAMP VOLTAGE (V_{SS})



NOTES
1. Each input to be tested separately.

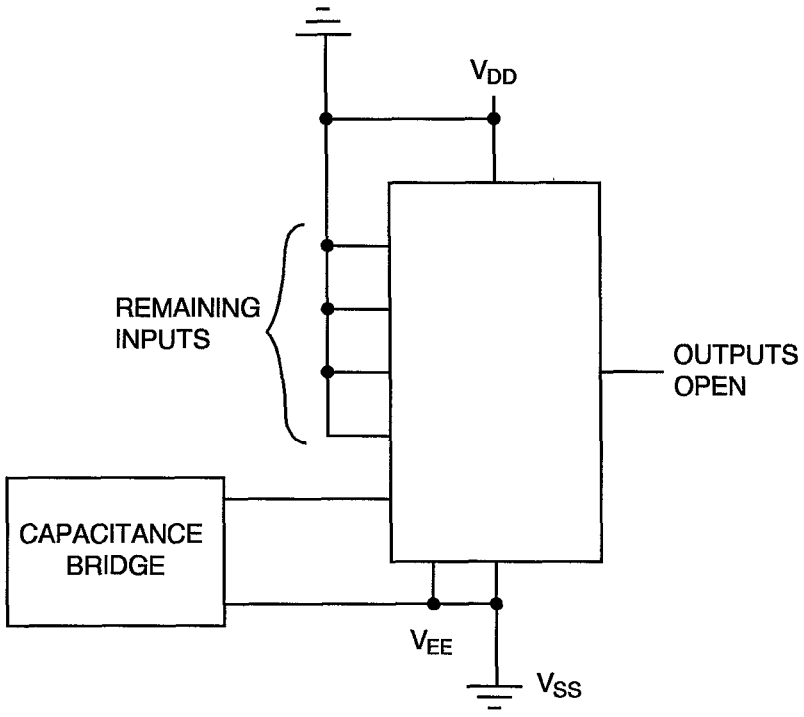
FIGURE 4(l) - INPUT CLAMP VOLTAGE (V_{DD})



NOTES
1. Each input to be tested separately.

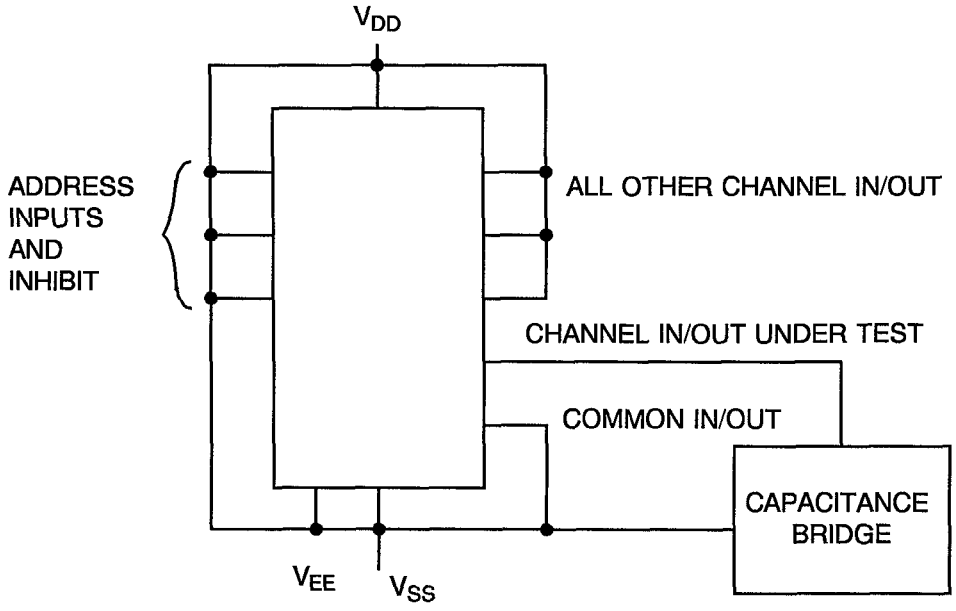
FIGURE 4 - CIRCUITS FOR ELECTRICAL MEASUREMENTS (CONTINUED)

FIGURE 4(m) - INPUT CAPACITANCE, ADDRESS AND INHIBIT



NOTES
1. f = 100kHz to 1MHz
2. Each input to be tested separately.

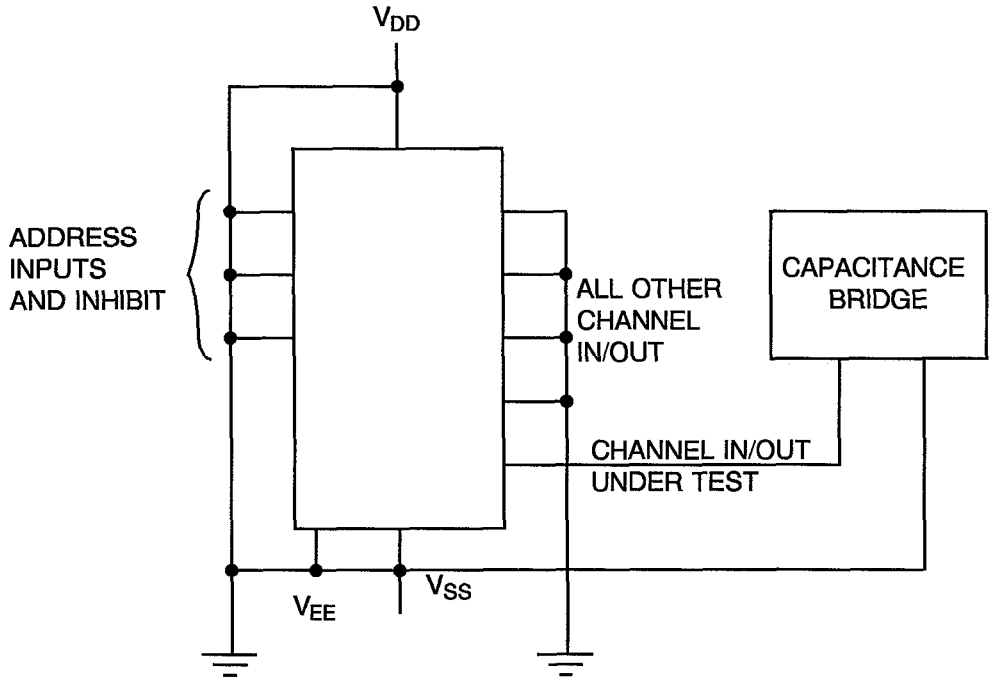
FIGURE 4(n) - CHANNEL INPUT CAPACITANCE



NOTES
1. f = 100kHz to 1MHz
2. Each input to be tested separately.

FIGURE 4 - CIRCUITS FOR ELECTRICAL MEASUREMENTS (CONTINUED)

FIGURE 4(o) - CHANNEL OUTPUT CAPACITANCE

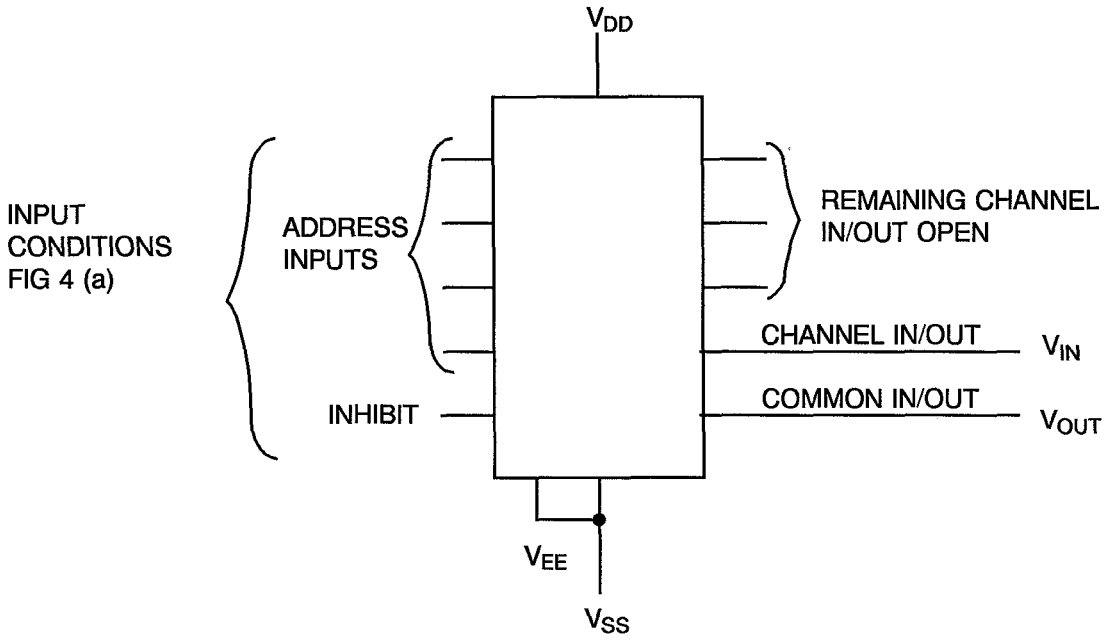


NOTES

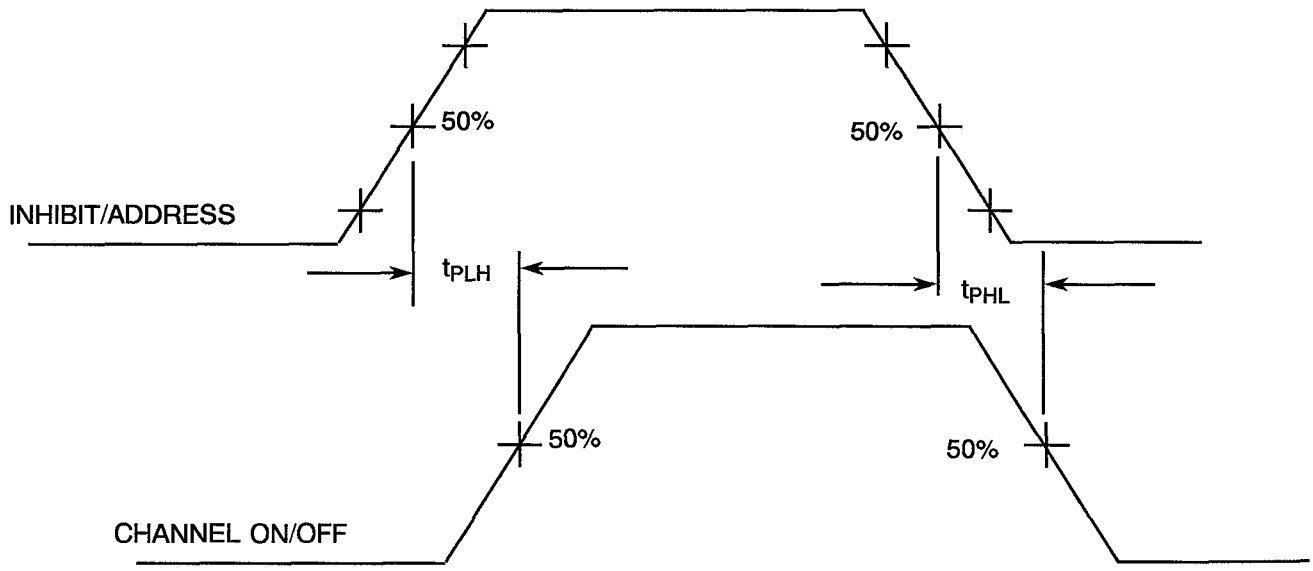
1. f = 100kHz to 1MHz
2. Each output to be tested separately.

FIGURE 4 - CIRCUITS FOR ELECTRICAL MEASUREMENTS (CONTINUED)

FIGURE 4(p) - PROPAGATION DELAY, INHIBIT OR ADDRESS INPUTS TO CHANNEL ON OR OFF



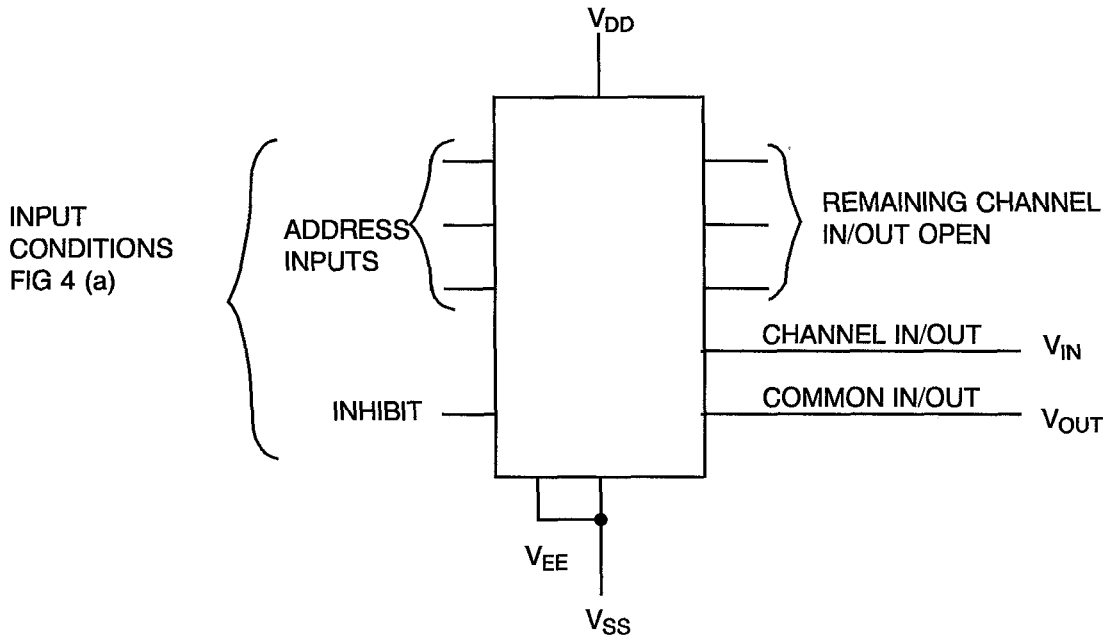
VOLTAGE WAVEFORMS



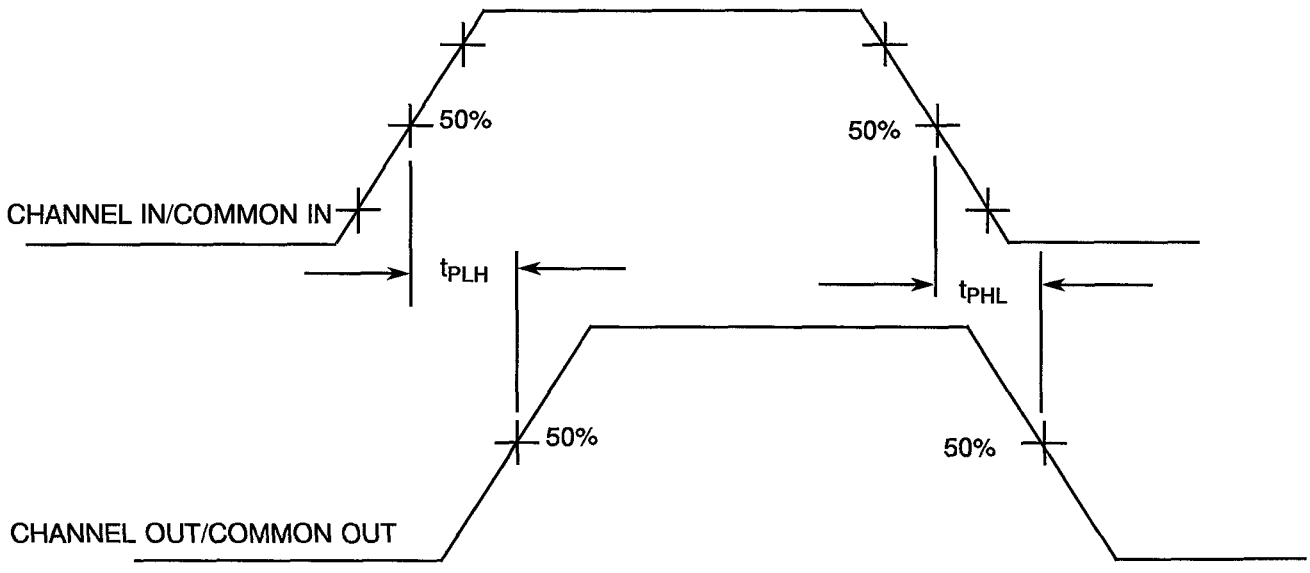
NOTES 1. Pulse Generator - V_P = 0 to V_{DD}, t_r and t_f ≤ 15ns, f = 500kHz.

FIGURE 4 - CIRCUITS FOR ELECTRICAL MEASUREMENTS (CONTINUED)

FIGURE 4(q) - PROPAGATION DELAY, CHANNEL OR COMMON IN TO COMMON OR CHANNEL OUT



VOLTAGE WAVEFORMS



NOTES 1. Pulse Generator - V_P = 0 to V_{DD}, t_r and t_f ≤ 15ns, f = 500kHz.

TABLE 4 - PARAMETER DRIFT VALUES

NO.	CHARACTERISTICS	SYMBOL	SPEC. AND/OR TEST METHOD	TEST CONDITIONS	CHANGE LIMITS (Δ)	UNIT
3 to 7	Quiescent Current	I_{DD}	As per Table 2	As per Table 2	±150	nA
Note 1	Channel on Resistance	R_{ON1}	As per Table 2	As per Table 2	±50	Ω
Note 2	Channel on Resistance	R_{ON2}	As per Table 2	As per Table 2	±15	Ω
276	Threshold Voltage N-Channel	V_{THN}	As per Table 2	As per Table 2	±0.3	V
277	Threshold Voltage P-Channel	V_{THP}	As per Table 2	As per Table 2	±0.3	V

NOTES

1. Test Numbers: 34, 42, 50, 58, 66, 74, 82, 90, 98, 106, 114, 122, 130, 138.
2. Test Numbers: 146, 154, 162, 170, 178, 186, 194, 202, 210, 218, 226, 234, 242, 250, 258, 266.

TABLE 5(a) - CONDITIONS FOR BURN-IN HIGH TEMPERATURE REVERSE BIAS, N-CHANNELS

NO.	CHARACTERISTICS	SYMBOL	CONDITION	UNIT
1	Ambient Temperature	T_{amb}	+125(+0-5)	°C
2	Channel In/Out (Pins D/F 1-2-4-5-11-12-14-15) (Pins C 1-2-5-6-14-15-17-19)	V_{CH}	V_{DD}	Vdc
3	Common In/Out (Pins D/F 3-13) (Pins C 4-16)	V_{COM}	Ground	Vdc
4	Inputs - (Pins D/F 6-9-10) (Pins C 7-11-12)	V_{IN}	V_{DD}	Vdc
5	Positive Supply Voltage (Pin D/F 16) (Pin C 20)	V_{DD}	15	Vdc
6	Negative Supply Voltage (Pin D/F 8) (Pin C 10)	V_{SS}	Ground	Vdc
7	Negative Supply Voltage (Pin D/F 7) (Pin C 9)	V_{EE}	Ground	Vdc

NOTES 1. Input Load = Protection Resistor = 2kΩ minimum to 47kΩ maximum.

TABLE 5(b) - CONDITIONS FOR BURN-IN HIGH TEMPERATURE REVERSE BIAS, P-CHANNELS

NO.	CHARACTERISTICS	SYMBOL	CONDITION	UNIT
1	Ambient Temperature	T_{amb}	+125(+0-5)	°C
2	Channel In/Out (Pins D/F 1-2-4-5-11-12-14-15) (Pins C 1-2-5-6-14-15-17-19)	V_{CH}	Ground	Vdc
3	Common In/Out (Pins D/F 3-13) (Pins C 4-16)	V_{COM}	Ground	Vdc
4	Inputs - (Pins D/F 6-9-10) (Pins C 7-11-12)	V_{IN}	Ground	Vdc
5	Positive Supply Voltage (Pin D/F 16) (Pin C 20)	V_{DD}	15	Vdc
6	Negative Supply Voltage (Pin D/F 8) (Pin C 10)	V_{SS}	Ground	Vdc
7	Negative Supply Voltage (Pin D/F 7) (Pin C 9)	V_{EE}	Ground	Vdc

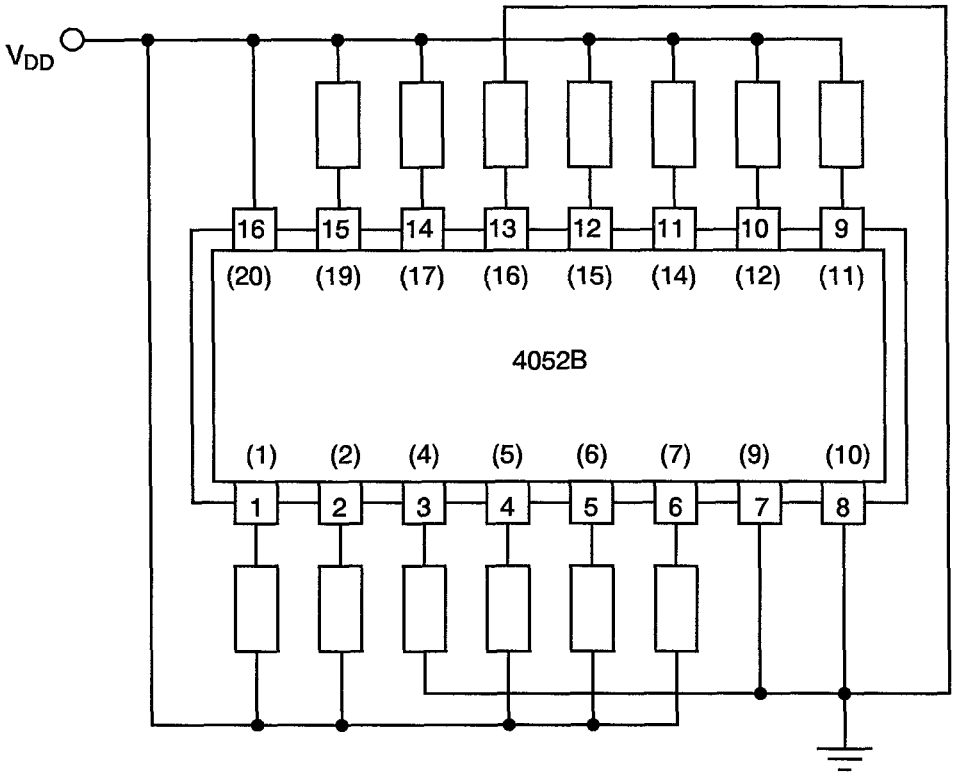
NOTES 1. Input Load = Protection Resistor = 2kΩ minimum to 47kΩ maximum.

TABLE 5(c) - CONDITIONS FOR BURN-IN DYNAMIC

NO.	CHARACTERISTICS	SYMBOL	CONDITIONS	UNIT
1	Ambient Temperature	T_{amb}	+125(+0-5)	°C
2	Channel In/Out (Pins D/F 1-2-4-5-11-12-14-15) (Pins C 1-2-5-6-14-15-17-19)	V_{CH}	V_{DD}	Vdc
3	Common In/Out (Pins D/F 3-13) (Pins C 4-16)	V_{COM}	Ground	Vdc
4	Inputs - (Pins D/F 6-9-10) (Pins C 7-11-12)	V_{IN}	V_{GEN}	Vac
5	Pulse Voltage (Binary Counter)	V_{GEN}	0 to V_{DD}	Vac
6	Pulse Frequency Binary Counter Square Wave	f	500k	Hz
7	Positive Supply Voltage (Pin D/F 16) (Pin C 20)	V_{DD}	15	Vdc
8	Negative Supply Voltage (Pin D/F 8) (Pin C 10)	V_{SS}	Ground	Vdc
9	Negative Supply Voltage (Pin D/F 7) (Pin C 9)	V_{EE}	Ground	Vdc

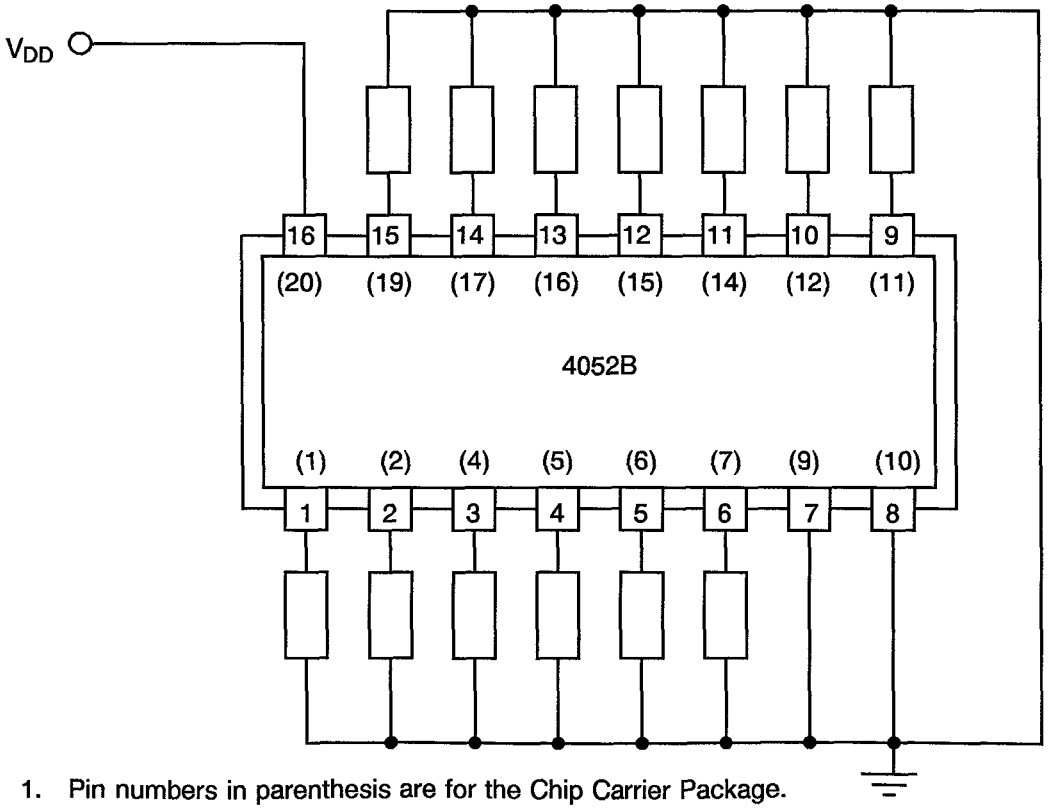
NOTES 1. Input Load = Output Load = 2kΩ minimum to 47kΩ maximum.

FIGURE 5(a) - ELECTRICAL CIRCUIT FOR BURN-IN HIGH TEMPERATURE REVERSE BIAS, N-CHANNELS



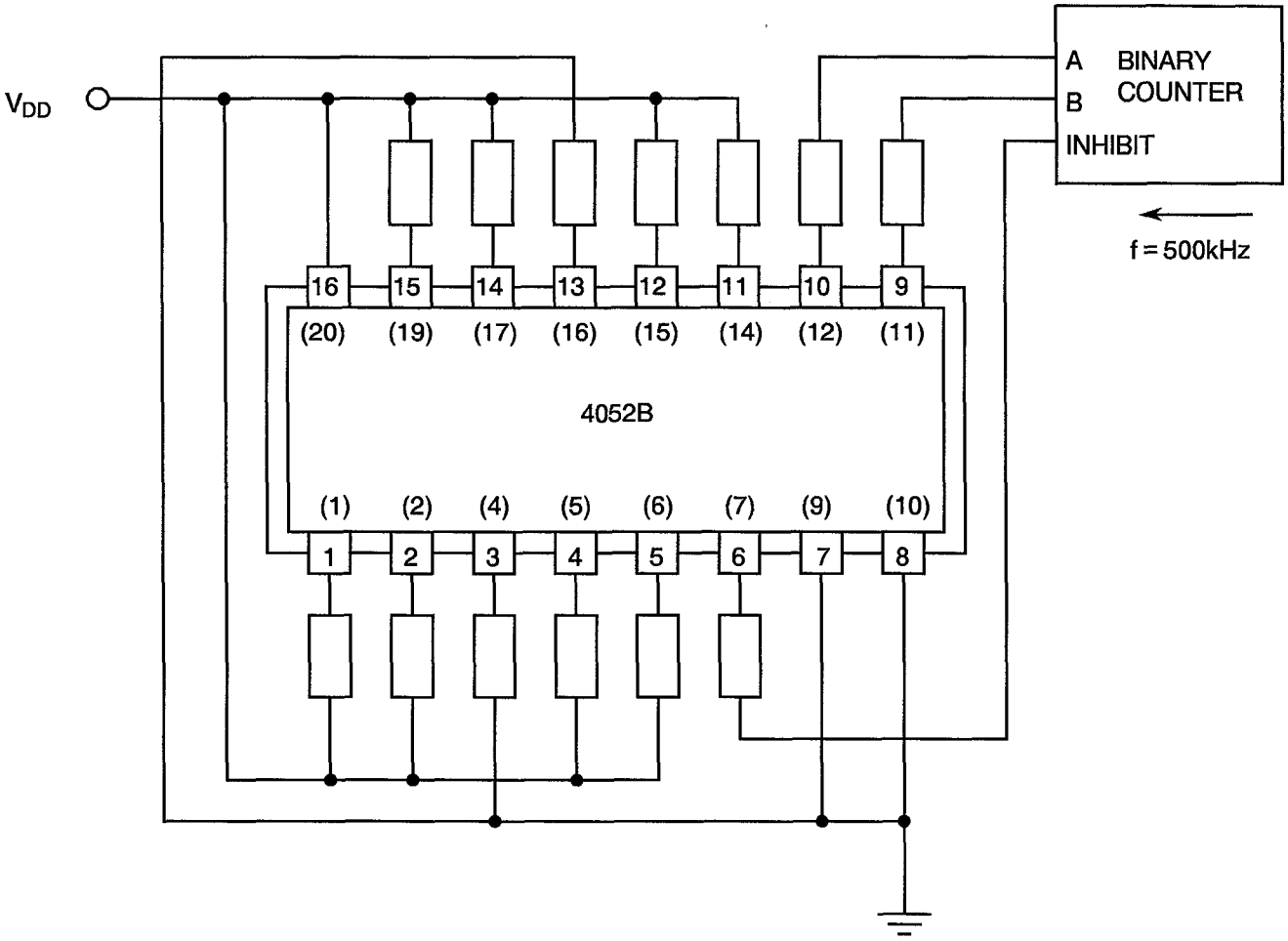
NOTES 1. Pin numbers in parenthesis are for the Chip Carrier Package.

FIGURE 5(b) - ELECTRICAL CIRCUIT FOR BURN-IN HIGH TEMPERATURE REVERSE BIAS, P-CHANNELS



NOTES 1. Pin numbers in parenthesis are for the Chip Carrier Package.

FIGURE 5(c) - ELECTRICAL CIRCUIT FOR BURN-IN DYNAMIC



NOTES 1. Pin numbers in parenthesis are for the Chip Carrier Package.

4.8 ENVIRONMENTAL AND ENDURANCE TESTS (CHARTS IV AND V OF ESA/SCC GENERIC SPECIFICATION NO. 9000)

4.8.1 Electrical Measurements on Completion of Environmental Tests

The parameters to be measured on completion of environmental tests are scheduled in Table 6. Unless otherwise stated, the measurements shall be performed at T_{amb} = +22±3 °C.

4.8.2 Electrical Measurements at Intermediate Points during Endurance Tests

The parameters to be measured at intermediate points during endurance tests are as scheduled in Table 6 of this specification.

4.8.3 Electrical Measurements on Completion of Endurance Tests

The parameters to be measured on completion of endurance testing are as scheduled in Table 6 of this specification. Unless otherwise stated, the measurements shall be performed at T_{amb} = +22±3 °C.

4.8.4 Conditions for Operating Life Test

The requirements for operating life testing are specified in Section 9 of ESA/SCC Generic Specification No. 9000. The conditions for operating life testing shall be as specified in Table 5(c) of this specification.

4.8.5 Electrical Circuits for Operating Life Tests

Circuits for use in performing the operating life tests are shown in Figure 5(c) of this specification.

4.8.6 Conditions for High Temperature Storage Test

The requirements for the high temperature storage test are specified in ESA/SCC Generic Specification No. 9000. The temperature to be applied shall be the maximum storage temperature specified in Table 1(b) of this specification.

TABLE 6 - ELECTRICAL MEASUREMENTS ON COMPLETION OF ENVIRONMENTAL TESTS AND AT INTERMEDIATE POINTS AND ON COMPLETION OF ENDURANCE TESTING

NO.	CHARACTERISTICS	SYMBOL	SPEC. AND/OR TEST METHOD	TEST CONDITIONS	CHANGE LIMITS (Δ)			UNIT
						MIN	MAX	
1	Functional Test	-	As per Table 2	As per Table 2	-	-	-	-
3 to 7	Quiescent Current	I_{DD}	As per Table 2	As per Table 2	±150	-	-	nA
8 to 10	Input Current Low Level Address or Inhibit	I_{IL}	As per Table 2	As per Table 2	-	-	-50	nA
11 to 13	Input Current High Level Address or Inhibit	I_{IH}	As per Table 2	As per Table 2	-	-	50	nA
14 to 21	Channel Off Leakage Current (Any Channel)	I_{OFF1}	As per Table 2	As per Table 2	-	-	-100	nA
30 to 31	Channel Off Leakage Current (All Channels)	I_{OFF3}	As per Table 2	As per Table 2	-	-	100	nA
34 to 145	Channel On Resistance	R_{ON1}	As per Table 2	As per Table 2	±50	-	-	Ω
146 to 273	Channel On Resistance	R_{ON2}	As per Table 2	As per Table 2	±15	-	-	Ω
274	Input Voltage Low Level (Noise Immunity) (Functional Test)	V_{IL1}	As per Table 2	As per Table 2	-	-	0.5	V
	Input Voltage High Level (Noise Immunity) (Functional Test)	V_{IH1}			-	4.5	-	
276	Threshold Voltage N-Channel	V_{THN}	As per Table 2	As per Table 2	±0.3	-	-	V
277	Threshold Voltage P-Channel	V_{THP}	As per Table 2	As per Table 2	±0.3	-	-	V

APPENDIX 'A'

AGREED DEVIATIONS FOR STMICROELECTRONICS (F)

ITEMS AFFECTED	DESCRIPTION OF DEVIATION
Para. 4.2.3	Para. 9.23, High Temperature Reverse Bias Burn-in: The temperature limits of MIL-STD-883, Para. 4.5.8(c) may be used. Para. 9.24, Power Burn-in: The temperature limits of MIL-STD-883, Para. 4.5.8(c) may be used.
Para. 4.2.4	Para. 9.21.1, Operating Life during Qualification Testing: The temperature limits of MIL-STD-883, Para. 4.5.8(c) may be used.
Para. 4.2.5	Para. 9.21.2, Operating Life during Lot Acceptance Testing: The temperature limits of MIL-STD-883, Para. 4.5.8(c) may be used.